Exhibit 8

Western Digital Accused Products

The following list of Accused Products is exemplary, non-exhaustive, and non-limiting. Greenthread asserts claims against all product variations and part numbers of the Accused Products.

	Solid State Drives (SSDs)
1.	WD_BLACK SN850X NVMe™ SSD
2.	SanDisk Extreme PRO Portable SSD V2
3.	My Passport TM SSD
4.	PRO-BLADE TRANSPORT
5.	WD_BLACK SN850 NVMe TM SSD for PS5 TM Consoles
6.	SanDisk Ultra 3D SSD
7.	SanDisk Extreme Portable SSD V2
8.	WD Blue SA510 SATA SSD 2.5"/7mm Cased
9.	PRO-BLADE SSD Mag
10.	WD_BLACK P40 Game Drive SSD
11.	WD Green SN350 NVMe™ SSD
12.	G-DRIVE SSD
13.	WD_BLACK SN770 NVMe™ SSD
14.	SanDisk® Portable SSD
15.	WD Red SN700 NVMe SSD
16.	WD Blue SA510 SATA SSD M.2 2280
17.	WD_BLACK™ D30 Game Drive SSD for Xbox™
18.	SanDisk SSD Plus
19.	WD_BLACK SN750 NVMe™ SSD
20.	WD Green™ SATA SSD 2.5"/7mm Cased
21.	WD Red™ SA500 NAS SATA SSD M.2 2280
22.	WD Elements™ SE SSD
23.	WD Blue™ SATA SSD 2.5"/7mm cased
24.	WD_BLACK P50 Game Drive SSD
25.	WD Red™ SA500 NAS SATA SSD 2.5"/7mm Cased
26.	WD_BLACK D50 Game Dock NVMe™ SSD

27.	WD Blue™ SATA SSD M.2 2280		
28.	WD_BLACK D30 Game Drive SSD		
29.	WD Green TM SATA SSD M.2 2280		
30.	OpenFlex Data24 NVMe-oF Storage Platform		
31.	Ultrastar Edge Transportable Edge Server		
32.	Ultrastar Edge-MR Ruggedized Edge Server		
33.	WD Gold™ Enterprise Class NVMe™ SSD		
34.	Ultrastar DC SN640		
35.	Ultrastar DC SA210		
36.	Ultrastar DC SN840		
37.	Ultrastar DC ZN540		
38.	Western Digital PC SN810 NVMe SSD		
39.	Western Digital CL SN520 NVMe SSD		
40.	WD Blue SN570 NVMe™ SSD		
41.	G-DRIVE™ PRO STUDIO SSD		
42.	PC SN540 NVMe SSD		
43.	PRO-G40 SSD		
44.	RapidFlex NVMe TM -oF Controllers - A2000		
45.	RapidFlex NVMe TM -oF Controllers - C2000		
46.	Western Digital PC SN740 NVMe™ SSD		
47.	Western Digital PC SA510 SATA SSD		
48.	Ultrastar DC SN650		
49.	PRO-BLADE STATION		
50.	SanDisk Extreme PRO M.2 NVMe 3D SSD		
51.	SanDisk Extreme Pro® Portable SSD		
52.	WD_BLACK - The Game Awards Limited Edition		
53.	WD_BLACK D50 Game Dock		
54.	WD_BLACK AN1500 NVMe SSD Add-in-Card		
55.	WD_BLACK SN850 NVMe™ SSD		
56.	WD® Gaming Drive Accelerated for Xbox One TM		
57.	WD_BLACK™ Call of Duty®: Black Ops Cold War Special Edition P50 Game Drive NVMe™ SSD		

58.	WD_BLACK™ Call of Duty®: Black Ops Cold War Special Edition SN850 NVMe™ SSD		
59.	easystore SSD		
60.	G-DRIVE ArmorLock SSD		
61.	G-DRIVE PRO SSD		
62.	G-RAID SHUTTLE SSD		
63.	WD_BLACK SN750 SE NVMe™ SSD Battlefield™ 2042 PC Game Code Bundle		
64.	RapidFlex NVMe TM -oF Controllers - A1000		
65.	RapidFlex NVMe TM -oF Controllers - C1000		
66.	PC SA530 3D NAND SATA SSD		
67.	PC SN530 NVMe SSD		
68.	PC SN730 NVMe SSD		
69.	easystore SSD Portable Storage		
70.	Industrial NVMe SSD		
	USB Flash Drives		
71.	SanDisk Ultra® Dual Drive Luxe USB Type-C TM Flash Drive		
72.	SanDisk Ultra Dual Drive Go USB Type-C, Rainbow Pride Limited Edition		
73.	SanDisk Ultra Eco™ USB 3.2 Flash Drive		
74.	Ultra Dual Drive USB 3.0		
75.	Ultra Dual Drive m3.0		
76.	SanDisk Ultra Luxe TM USB 3.1 Flash Drive		
77.	SanDisk Ultra Flair USB 3.0 Flash Drive		
78.	SanDisk Ultra USB 3.0 Flash Drive		
79.	Cruzer Glide 3.0 USB Flash Drive		
80.	Cruzer Force USB Flash Drive		
81.	Cruzer Glide USB Flash Drive		
82.	Cruzer Blade USB Flash Drive		
83.	Cruzer Fit USB Flash Drive		
84.	SanDisk Ultra Fit USB 3.2 Flash Drive		
85.	Ultra Dual Drive Go USB Type-C TM		

86.	SANDISK® CRUZER SPARK™ USB 2.0 Flash Drive
87.	SanDisk Ultra® USB Type-C TM Flash Drive
88.	SanDisk® Ultra Shift™ USB 3.0 Flash Drive
89.	iXpand™ Flash Drive Flip
90.	SanDisk® iXpand® Flash Drive Luxe
91.	SanDisk Extreme PRO® USB 3.2 Solid State Flash Drive
92.	easystore USB
93.	iXpand Flash Drive Go
94.	Ultra Dual Drive USB Type-C
95.	SanDisk Extreme Go USB 3.1 Flash Drive
96.	SanDisk Extreme Go USB Drive
	Memory Cards
97.	SanDisk Extreme® microSDXCTM UHS-I CARD
98.	SanDisk Extreme Pro CFexpress® Card Type B
99.	Nintendo®-Licensed Memory Cards For Nintendo Switch™
100.	SanDisk MAX ENDURANCE microSD TM Card
101.	SanDisk microSDXC TM card for Nintendo Switch TM , Fortnite® Edition
102.	SanDisk Extreme SD UHS-I Card
103.	SanDisk Extreme PRO SDXC™ UHS-II Card
104.	SanDisk Professional PRO-READER SD and microSD™
105.	SanDisk Extreme PRO microSDXCTM UHS-I CARD
106.	SanDisk Extreme PRO® SDHC TM and SDXC TM UHS-II cards
107.	PRO-CINEMA CFexpress® VPG400 Type B
108.	SanDisk Extreme SD UHS-I Card (Up to 150 MBPs)
109.	SanDisk Extreme PRO® SDHC TM And SDXC TM UHS-I Card (Up to 170 MBPs)
110.	SanDisk Extreme microSDXC™ UHS-I CARD (Up to 160 MBPs)
111.	SanDisk Extreme PRO microSDXC TM UHS-I CARD (Up to 170 MBPs)
112.	SanDisk Extreme microSD™ Card for Mobile Gaming (Up to 160 MBPs)
113.	SanDisk Ultra® microSD TM Card for Chromebook
114.	SanDisk Ultra microSD with SD Adapter
115.	SanDisk Ultra® SDHC TM UHS-I card and SDXC TM UHS-I card

117. SanDisk High Endurance microSD™ Card 118. WD Purple SC QD101 Ultra Endurance microSD Card 119. SanDisk Extreme microSD™ Card for Mobile Gaming 120. SanDisk Extreme Pro CFexpress® Card Type B 121. SanDisk Ultra® SDHC™ UHS-I card and SDXC™ UHS-I card (Up to 120MBPs) 122. SanDisk Ultra microSD with SD Adapter (Up to 120MBPs) 123. Extreme CompactFlash Memory Card 124. Extreme Pro CompactFlash Memory Card 125. SanDisk Extreme PRO CFast 2.0 Memory Card 126. SanDisk Extreme PRO SDHC™ And SDXC™ UHS-I Card 127. SanDisk Ultra® microSD™ Card for Chromebook (Up to 120MBPs) 128. SanDisk Extreme PRO® SDHC™ And SDXC™ UHS-I Card 129. SanDisk Ultra microSD UHS-I Card 130. Ultra SDHC/SDXC Memory Card 131. SanDisk® microSDXC™ card for Nintendo Switch™, Apex Legends 132. SanDisk Extreme PRO® UHS-II Card 133. Commercial Edge SD Card 134. Commercial Edge microSD Card 135. Industrial microSD Card 136. Industrial SD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card 140. WD Gold™ Enterprise Class NVMe™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	116.	SDHC/SDXC Memory Card
119. SanDisk Extreme microSD™ Card for Mobile Gaming 120. SanDisk Extreme Pro CFexpress® Card Type B 121. SanDisk Ultra® SDHC™ UHS-I card and SDXC™ UHS-I card (Up to 120MBPs) 122. SanDisk Ultra microSD with SD Adapter (Up to 120MBPs) 123. Extreme CompactFlash Memory Card 124. Extreme Pro CompactFlash Memory Card 125. SanDisk Extreme PRO CFast 2.0 Memory Card 126. SanDisk Extreme PRO SDHC™ And SDXC™ UHS-I Card 127. SanDisk Ultra® microSD™ Card for Chromebook (Up to 120MBPs) 128. SanDisk Extreme PRO® SDHC™ And SDXC™ UHS-I Card 129. SanDisk Ultra microSD UHS-I Card 130. Ultra SDHC/SDXC Memory Card 131. SanDisk® microSDXC™ card for Nintendo Switch™, Apex Legends 132. SanDisk Extreme PRO® UHS-II Card 133. Commercial Edge SD Card 134. Commercial Edge microSD Card 135. Industrial microSD Card 136. Industrial microSD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ SD Card 140. WD Gold™ Enterprise Class NVMe™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	117.	SanDisk High Endurance microSD™ Card
120. SanDisk Extreme Pro CFexpress® Card Type B 121. SanDisk Ultra® SDHC™ UHS-I card and SDXC™ UHS-I card (Up to 120MBPs) 122. SanDisk Ultra microSD with SD Adapter (Up to 120MBPs) 123. Extreme CompactFlash Memory Card 124. Extreme Pro CompactFlash Memory Card 125. SanDisk Extreme PRO CFast 2.0 Memory Card 126. SanDisk Extreme PRO SDHC™ And SDXC™ UHS-I Card 127. SanDisk Ultra® microSD™ Card for Chromebook (Up to 120MBPs) 128. SanDisk Extreme PRO® SDHC™ And SDXC™ UHS-I Card 129. SanDisk Ultra microSD UHS-I Card 130. Ultra SDHC/SDXC Memory Card 131. SanDisk® microSDXC™ card for Nintendo Switch™, Apex Legends 132. SanDisk Extreme PRO® UHS-II Card 133. Commercial Edge SD Card 134. Commercial Edge microSD Card 135. Industrial microSD Card 136. Industrial SD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card 140. WD Gold™ Enterprise Class NVMe™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	118.	WD Purple SC QD101 Ultra Endurance microSD Card
121. SanDisk Ultra® SDHC™ UHS-I card and SDXC™ UHS-I card (Up to 120MBPs) 122. SanDisk Ultra microSD with SD Adapter (Up to 120MBPs) 123. Extreme CompactFlash Memory Card 124. Extreme Pro CompactFlash Memory Card 125. SanDisk Extreme PRO CFast 2.0 Memory Card 126. SanDisk Extreme PRO SDHC™ And SDXC™ UHS-I Card 127. SanDisk Ultra® microSD™ Card for Chromebook (Up to 120MBPs) 128. SanDisk Extreme PRO® SDHC™ And SDXC™ UHS-I Card 129. SanDisk Ultra microSD UHS-I Card 130. Ultra SDHC/SDXC Memory Card 131. SanDisk® microSDXC™ card for Nintendo Switch™, Apex Legends 132. SanDisk Extreme PRO® UHS-II Card 133. Commercial Edge SD Card 134. Commercial Edge microSD Card 135. Industrial microSD Card 136. Industrial SD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card 140. WD Gold™ Enterprise Class NVMe™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	119.	SanDisk Extreme microSD TM Card for Mobile Gaming
120MBPs) 122. SanDisk Ultra microSD with SD Adapter (Up to 120MBPs) 123. Extreme CompactFlash Memory Card 124. Extreme Pro CompactFlash Memory Card 125. SanDisk Extreme PRO CFast 2.0 Memory Card 126. SanDisk Extreme PRO SDHC™ And SDXC™ UHS-I Card 127. SanDisk Ultra® microSD™ Card for Chromebook (Up to 120MBPs) 128. SanDisk Extreme PRO® SDHC™ And SDXC™ UHS-I Card 129. SanDisk Ultra microSD UHS-I Card 130. Ultra SDHC/SDXC Memory Card 131. SanDisk® microSDXC™ card for Nintendo Switch™, Apex Legends 132. SanDisk Extreme PRO® UHS-II Card 133. Commercial Edge SD Card 134. Commercial Edge microSD Card 135. Industrial microSD Card 136. Industrial SD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ SD Card 140. WD Gold™ Enterprise Class NVMe™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	120.	SanDisk Extreme Pro CFexpress® Card Type B
123. Extreme CompactFlash Memory Card 124. Extreme Pro CompactFlash Memory Card 125. SanDisk Extreme PRO CFast 2.0 Memory Card 126. SanDisk Extreme PRO SDHC™ And SDXC™ UHS-I Card 127. SanDisk Ultra® microSD™ Card for Chromebook (Up to 120MBPs) 128. SanDisk Extreme PRO® SDHC™ And SDXC™ UHS-I Card 129. SanDisk Ultra microSD UHS-I Card 130. Ultra SDHC/SDXC Memory Card 131. SanDisk® microSDXC™ card for Nintendo Switch™, Apex Legends 132. SanDisk Extreme PRO® UHS-II Card 133. Commercial Edge SD Card 134. Commercial Edge microSD Card 135. Industrial microSD Card 136. Industrial SD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card 140. WD Gold™ Enterprise Class NVMc™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	121.	\ <u>1</u>
124. Extreme Pro CompactFlash Memory Card 125. SanDisk Extreme PRO CFast 2.0 Memory Card 126. SanDisk Extreme PRO SDHC™ And SDXC™ UHS-I Card 127. SanDisk Ultra® microSD™ Card for Chromebook (Up to 120MBPs) 128. SanDisk Extreme PRO® SDHC™ And SDXC™ UHS-I Card 129. SanDisk Ultra microSD UHS-I Card 130. Ultra SDHC/SDXC Memory Card 131. SanDisk® microSDXC™ card for Nintendo Switch™, Apex Legends 132. SanDisk Extreme PRO® UHS-II Card 133. Commercial Edge SD Card 134. Commercial Edge microSD Card 135. Industrial microSD Card 136. Industrial SD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card 140. WD Gold™ Enterprise Class NVMe™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	122.	SanDisk Ultra microSD with SD Adapter (Up to 120MBPs)
125. SanDisk Extreme PRO CFast 2.0 Memory Card 126. SanDisk Extreme PRO SDHC™ And SDXC™ UHS-I Card 127. SanDisk Ultra® microSD™ Card for Chromebook (Up to 120MBPs) 128. SanDisk Extreme PRO® SDHC™ And SDXC™ UHS-I Card 129. SanDisk Ultra microSD UHS-I Card 130. Ultra SDHC/SDXC Memory Card 131. SanDisk® microSDXC™ card for Nintendo Switch™, Apex Legends 132. SanDisk Extreme PRO® UHS-II Card 133. Commercial Edge SD Card 134. Commercial Edge microSD Card 135. Industrial microSD Card 136. Industrial SD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card 140. WD Gold™ Enterprise Class NVMe™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	123.	Extreme CompactFlash Memory Card
126. SanDisk Extreme PRO SDHC TM And SDXC TM UHS-I Card 127. SanDisk Ultra® microSD TM Card for Chromebook (Up to 120MBPs) 128. SanDisk Extreme PRO® SDHC TM And SDXC TM UHS-I Card 129. SanDisk Ultra microSD UHS-I Card 130. Ultra SDHC/SDXC Memory Card 131. SanDisk® microSDXC TM card for Nintendo Switch TM , Apex Legends 132. SanDisk Extreme PRO® UHS-II Card 133. Commercial Edge SD Card 134. Commercial Edge microSD Card 135. Industrial microSD Card 136. Industrial SD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card 140. WD Gold TM Enterprise Class NVMc TM SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	124.	Extreme Pro CompactFlash Memory Card
127. SanDisk Ultra® microSD™ Card for Chromebook (Up to 120MBPs) 128. SanDisk Extreme PRO® SDHC™ And SDXC™ UHS-I Card 129. SanDisk Ultra microSD UHS-I Card 130. Ultra SDHC/SDXC Memory Card 131. SanDisk® microSDXC™ card for Nintendo Switch™, Apex Legends 132. SanDisk Extreme PRO® UHS-II Card 133. Commercial Edge SD Card 134. Commercial Edge microSD Card 135. Industrial microSD Card 136. Industrial SD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card 140. WD Gold™ Enterprise Class NVMe™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	125.	SanDisk Extreme PRO CFast 2.0 Memory Card
128. SanDisk Extreme PRO® SDHC™ And SDXC™ UHS-I Card 129. SanDisk Ultra microSD UHS-I Card 130. Ultra SDHC/SDXC Memory Card 131. SanDisk® microSDXC™ card for Nintendo Switch™, Apex Legends 132. SanDisk Extreme PRO® UHS-II Card 133. Commercial Edge SD Card 134. Commercial Edge microSD Card 135. Industrial microSD Card 136. Industrial SD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card 140. WD Gold™ Enterprise Class NVMe™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	126.	SanDisk Extreme PRO SDHC TM And SDXC TM UHS-I Card
129. SanDisk Ultra microSD UHS-I Card 130. Ultra SDHC/SDXC Memory Card 131. SanDisk® microSDXC™ card for Nintendo Switch™, Apex Legends 132. SanDisk Extreme PRO® UHS-II Card 133. Commercial Edge SD Card 134. Commercial Edge microSD Card 135. Industrial microSD Card 136. Industrial SD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card Data Center Storage 140. WD Gold™ Enterprise Class NVMe™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	127.	SanDisk Ultra® microSD TM Card for Chromebook (Up to 120MBPs)
130. Ultra SDHC/SDXC Memory Card 131. SanDisk® microSDXC™ card for Nintendo Switch™, Apex Legends 132. SanDisk Extreme PRO® UHS-II Card 133. Commercial Edge SD Card 134. Commercial Edge microSD Card 135. Industrial microSD Card 136. Industrial SD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card Data Center Storage 140. WD Gold™ Enterprise Class NVMe™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	128.	SanDisk Extreme PRO® SDHCTM And SDXCTM UHS-I Card
131. SanDisk® microSDXC™ card for Nintendo Switch™, Apex Legends 132. SanDisk Extreme PRO® UHS-II Card 133. Commercial Edge SD Card 134. Commercial Edge microSD Card 135. Industrial microSD Card 136. Industrial SD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card Data Center Storage 140. WD Gold™ Enterprise Class NVMe™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	129.	SanDisk Ultra microSD UHS-I Card
132. SanDisk Extreme PRO® UHS-II Card 133. Commercial Edge SD Card 134. Commercial Edge microSD Card 135. Industrial microSD Card 136. Industrial SD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card Data Center Storage 140. WD Gold™ Enterprise Class NVMe™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	130.	Ultra SDHC/SDXC Memory Card
133. Commercial Edge SD Card 134. Commercial Edge microSD Card 135. Industrial microSD Card 136. Industrial SD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card Data Center Storage 140. WD Gold™ Enterprise Class NVMe™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	131.	SanDisk® microSDXC TM card for Nintendo Switch TM , Apex Legends
134. Commercial Edge microSD Card 135. Industrial microSD Card 136. Industrial SD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card Data Center Storage 140. WD Gold TM Enterprise Class NVMe TM SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	132.	SanDisk Extreme PRO® UHS-II Card
135. Industrial microSD Card 136. Industrial SD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card Data Center Storage 140. WD Gold TM Enterprise Class NVMe TM SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	133.	Commercial Edge SD Card
136. Industrial SD Card 137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card Data Center Storage 140. WD Gold TM Enterprise Class NVMe TM SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	134.	Commercial Edge microSD Card
137. Automotive SD Card 138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card Data Center Storage 140. WD Gold TM Enterprise Class NVMe TM SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	135.	Industrial microSD Card
138. Connected Home Edge+ SD Card 139. Connected Home Edge+ microSD Card Data Center Storage 140. WD Gold™ Enterprise Class NVMe™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	136.	Industrial SD Card
139. Connected Home Edge+ microSD Card Data Center Storage 140. WD Gold™ Enterprise Class NVMe™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	137.	Automotive SD Card
Data Center Storage 140. WD Gold™ Enterprise Class NVMe™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS	138.	Connected Home Edge+ SD Card
 140. WD Gold™ Enterprise Class NVMe™ SSD 141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS 	139.	Connected Home Edge+ microSD Card
141. Embedded Flash 142. Connected Home e.MMC 143. Automotive e.MMC 144. Commercial UFS		Data Center Storage
142. Connected Home e.MMC143. Automotive e.MMC144. Commercial UFS	140.	WD Gold™ Enterprise Class NVMe™ SSD
143. Automotive e.MMC 144. Commercial UFS	141.	Embedded Flash
144. Commercial UFS	142.	Connected Home e.MMC
	143.	Automotive e.MMC
145 Automotive LIEC	144.	Commercial UFS
143. Automotive UFS	145.	Automotive UFS

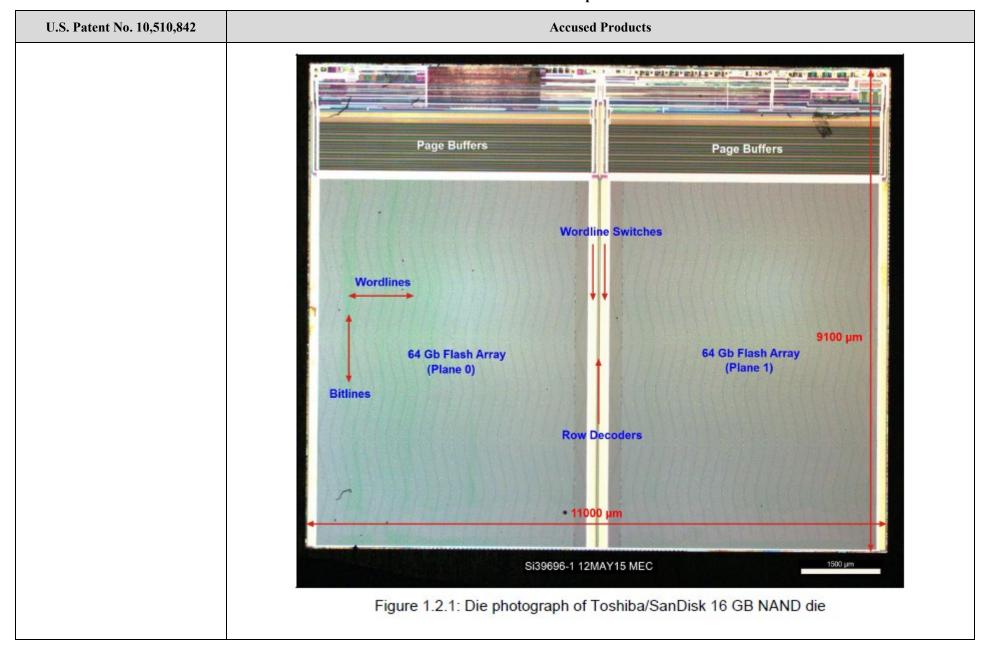
146.	Commercial e.MMC
147.	Industrial UFS
148.	Industrial e.MMC
	Network Attached Storage
149.	Network Attached Storage WD Red SN700 NVMe SSD

U.S. Patent No. 10,510,842	Accused Products		
[Claim 1, Preamble] A semiconductor device, comprising: To the extent the preamble is a limitation, the Western Digital Accused Products include a semiconductor device. shown below, the Defendants sell various examples of flash memory devices (e.g., microSD/SD cards and solid-st of which contain flash memory).			devices (e.g., microSD/SD cards and solid-state drives (SSDs), both
	Below are examples of SanDisk SDHC (SD High Capacity) flash memory cards:		emory cards:
		Is this relevant? i 0 0	Is this relevant? i O
		Compare	Compare
		SanDisk SOHC Card © E	SanDisk SDHC Card © ===================================
		SanDisk - Flash memory card - 32 GB - Class 4 - SDHC	SanDisk - Flash memory card - 16 GB - Class 4 - SDHC
		★★★★ 4.2 (28)	★★★★ 4.5 (15)
		\$10.99	\$10.99
		Get it as soon as Monday, May 2 View Delivery Dates for 20170	Get it as soon as Monday, May 2 View Delivery Dates for 20170
		Manufacturer Part SDSDB-032G-A46 Dell Part A7610910	Manufacturer Part SDSDB-016G-A46 Dell Part A7610909
		View Details	View Details
	See https://www.dell.com/en-us/sea		
	Below is an example of a SanDisk	22D:	

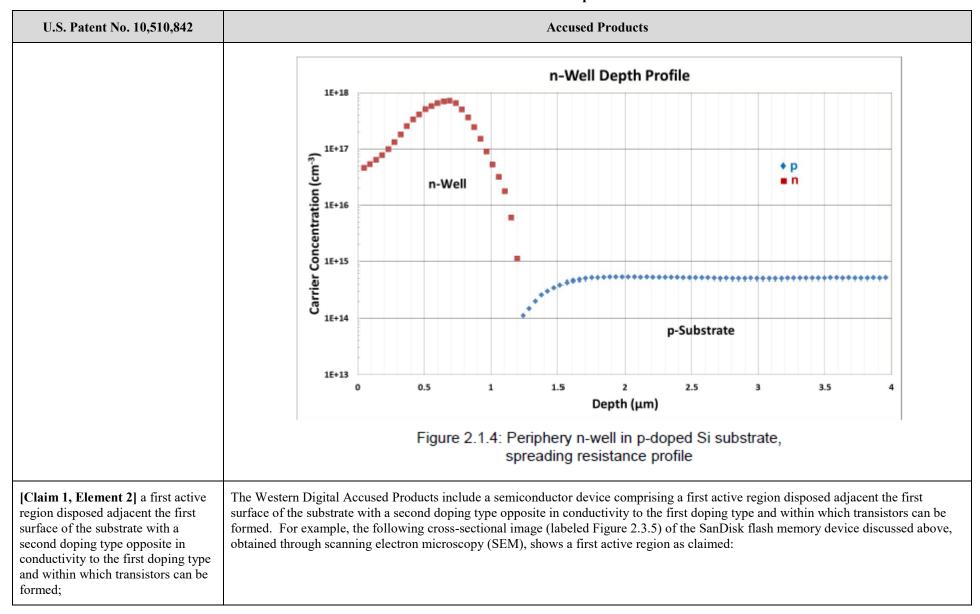
U.S. Patent No. 10,510,842	Accused Products		
		SanDisk Extreme Portable - Solid state drive - 500 GB - external (portable) - USB 3.1 Gen 2	
		Your life's an adventure. The SanDisk Extreme Portable SSD fits your mobile lifestyle and accelerates every move. Nearly 2x as fast as our previous generation!	
		\$119.99 You Save \$20.00 (14%)	
	Santjux	Get it as soon as Friday, Apr 29 View Delivery Dates for 95050	
		Financing As low as \$20/mo.^ Apply for Credit	
		♥ Up to \$3 back in rewards	
		1 V Add to Cart	
		Manufacturer Part SDSSDE61-500G-G25 Dell Part AB609642 Order Code Ab609642 SanDisk Compare	
		Compare	
	Tec	ch Specs	
	Gen	neral	
	Devi	се Туре	
	Solid	state drive - external (portable)	
	See https://www.dell.com/en-us/shop/sandisk-extreme-portable-solid-state-drive-500-gb-external-portable-usb-31-gen-2/apd/ab609642/storage-drives-media		
	Below are examples of Western Digital SSDs:		

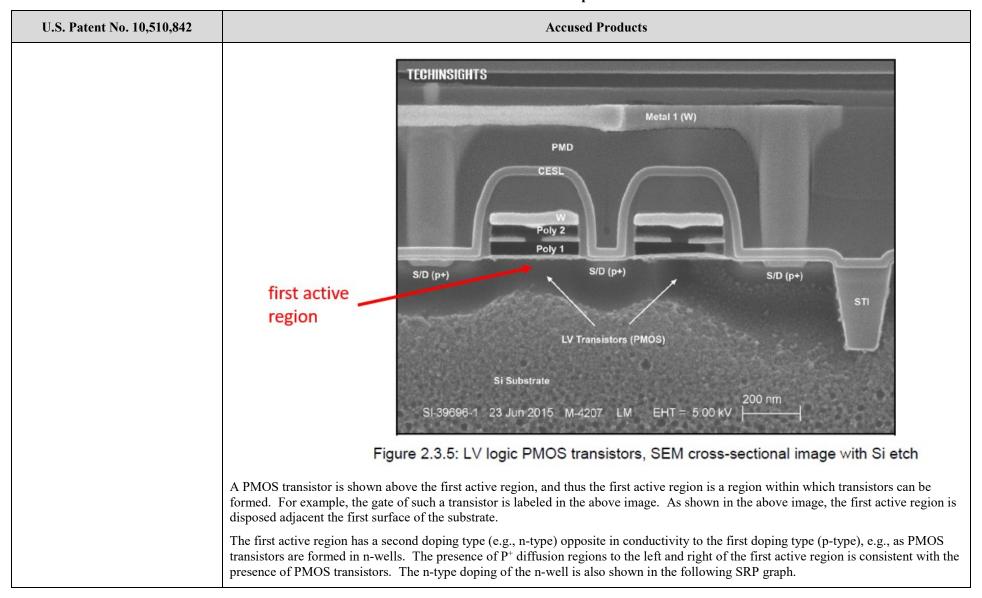
U.S. Patent No. 10,510,842	Accused Products		
	Is this relevant?	Is this relevant? i	Is this relevant? i o 50
	Compare	Compare	Compare
	WD BLUE: Source SATA SSD Solid Stave Drive	and the same of th	Oall or Chat
	WD Blue 3D NAND SATA SSD WDS200T2B0A - Solid state drive - 2 TB - internal - 2.5-inch - SATA 6Gb/s	WD Blue 3D NAND SATA SSD WDS200T2B0B - Solid state drive - 2 TB - internal - M.2 2280 - SATA 6Gb/s	WD Blue 3D NAND SATA SSD WDS100T2B0B - Solid state drive - 1 TB - internal - M.2 2280 - SATA 6Gb/s
	Estimated Value \$269.99 \$229.99 You Save \$40.00 (15%)	Estimated Value \$263.99 \$243.99 You Save \$20.00 (8%)	*** * * 4.6 (17) Estimated Value \$129.99 \$117.99 You Save \$12.00 (9%)
	Get it as soon as Monday, May 2 View Delivery Dates for 20170	Get it as soon as Monday, May 2 View Delivery Dates for 20170	Get it as soon as Monday, May 2 View Delivery Dates for 20170
	Manufacturer Part WDS200T2B0A Dell Part A9935209	Manufacturer Part WDS200T2B0B Dell Part A9935210	Manufacturer Part WDS100T2B0B Dell Part A9935211
	View Details	View Details	View Details
	See https://www.dell.com/en-us/search/wd%20ssd%20blue%203d Such SSDs, like the other flash memory devices (e.g., SD/microSD cards), are semiconductor devices.		

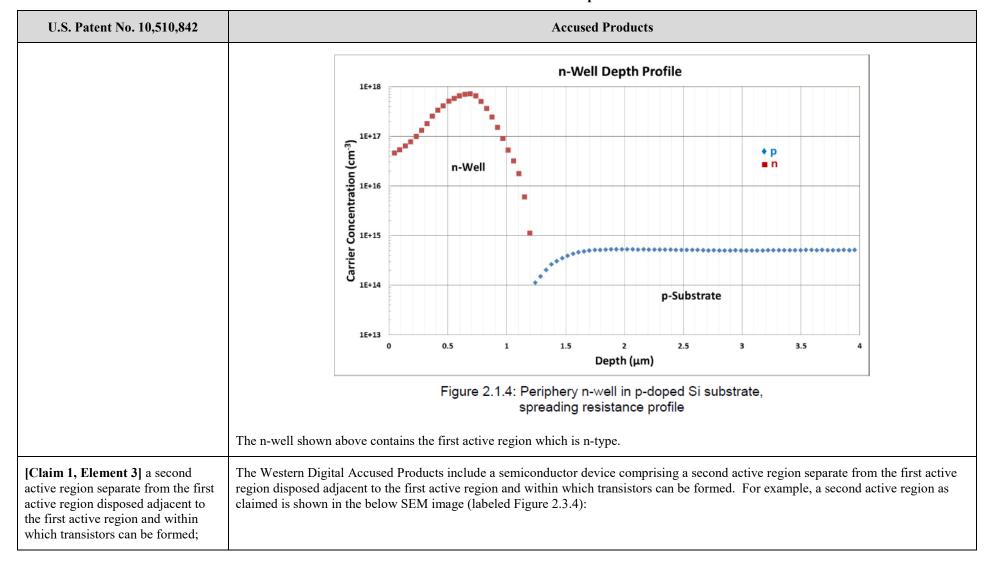
U.S. Patent No. 10,510,842	Accused Products		
	What is a flash solid-state drive (SSD)?		
	A flash solid-state drive (SSD) is a non-volatile storage device that stores persistent data in		
	flash memory. There are two types of <u>flash memory</u> used in SSDs NAND and NOR.		
	See https://www.techtarget.com/searchstorage/definition/flash-based-solid-state-drive-SSD		
	Solid state refers to electronic circuitry that is built entirely of semiconductors. The term was originally used to define those electronics, such as a transistor radio that used semiconductors rather than vacuum tubes in its construction.		
	Most electronics today are built around semiconductors and chips. A solid state drive uses, as its primary storage medium, semiconductors rather than the magnetic platters of a conventional hard drive.		
	See https://www.lifewire.com/solid-state-drive-833448		
	The above SanDisk flash memory card and the above SanDisk and Western Digital SSDs are representative examples of the Western Digital Accused Products, e.g., because all of these devices include a flash memory.		
	A SanDisk 15 nm node NAND flash memory has been analyzed via tear-down and is described in this claim chart and other infringement contention claim charts (e.g., Exhibits A-1 through A-6), as explained below, as a representative example of the Western Digital Accused Products. Upon information and belief, other flash memory devices would have similarly been advantageously designed to move carriers (e.g., towards the substrate) and achieve the performance enhancements described and claimed in the '842 patent (and the other asserted patents). For example, other flash memory devices would similarly have been designed with a dopant gradient in order to improve performance characteristics such as on and off switching times and other performance enhancements described in the Abstract of the '842 patent (and the other asserted patents). Therefore, upon information and belief, other Western Digital Accused Products contain similar features as the SanDisk 15 nm node NAND flash memory, and function in a similar way, with respect to the features claimed in the asserted claims.		
	This claim chart is based on publicly available information, and additional information regarding these and other accused products is expected to be obtained through discovery.		
[Claim 1, Element 1] a substrate of a first doping type at a first doping level having first and second surfaces;			

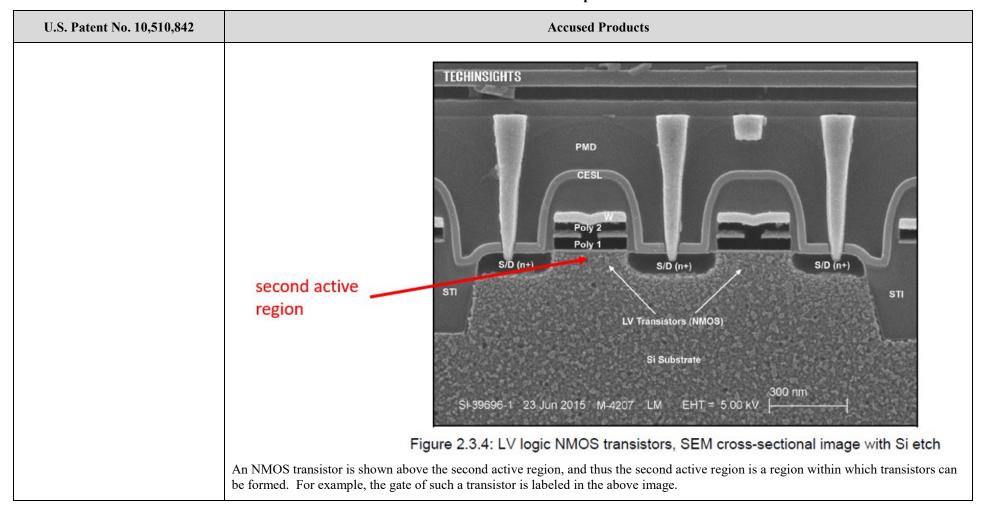


U.S. Patent No. 10,510,842	Accused Products		
	The following image of a cross-section of the flash memory die, obtained through scanning electron microscopy (SEM), shows the die having a thickness of 147.2 µm in this example. The flash memory die includes a substrate having first and second surfaces, as shown below:		
	TECHINSIGHTS Bond Pad first surface		
	NAND Die Edge 147.2 μm Substrate		
	substrate		
	SI-39696-1 28 May 2015 M-4207 LM EHT = 5.00 kV Second surface		
	Figure 1.2.3: Die thickness, SEM cross-sectional image		
	A thickness (depth) of, e.g., 147.2 μm is consistent with the presence of a substrate.		
	Spreading resistance profile (SRP) analysis conducted on the flash memory shows that the substrate is p-type (a first doping type) and has a first doping level (<i>see</i> concentration of p-type substrate in below graph).		



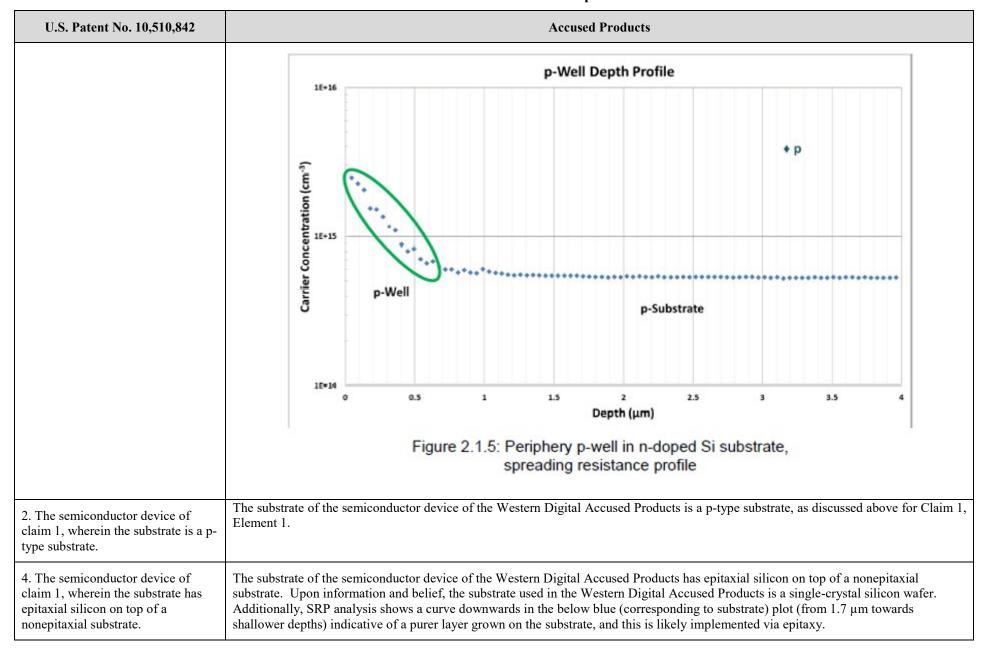


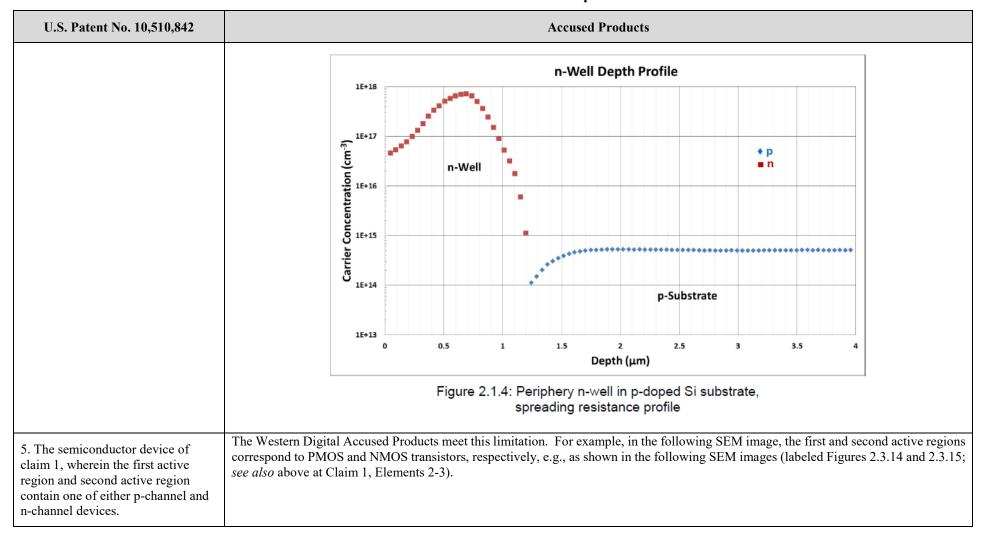


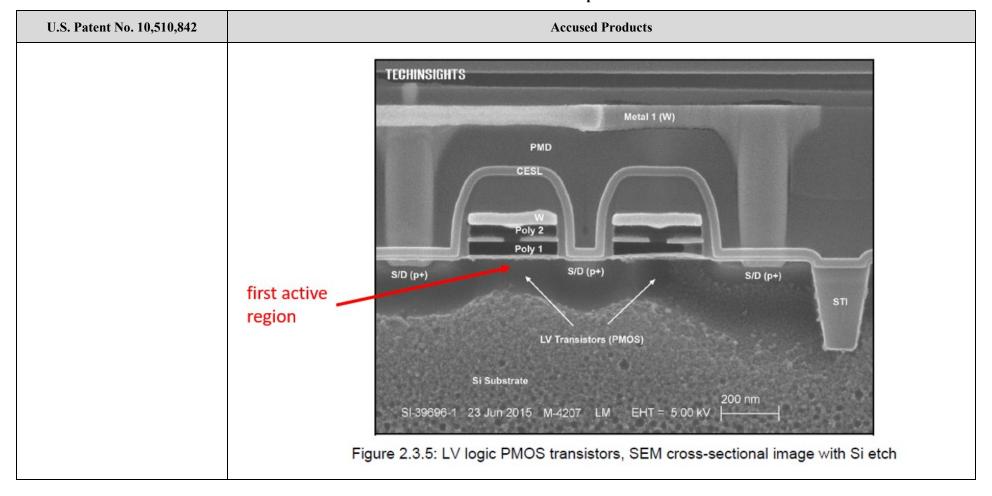


U.S. Patent No. 10,510,842	Accused Products		
	first active region St-3969651 23 Jun 2015 M-4207 LM EHT = 5 00 kV Cross-sectional image with Si etch As shown in the above SEM image (labeled Figure 2.3.9), the second active region (which is shown near an NMOS transistor) is separate from the first active region (which is shown near a PMOS transistor) and is disposed adjacent to the first active region.		
[Claim 1, Element 4] transistors formed in at least one of the first active region or second active region; and	The Western Digital Accused Products include a semiconductor device comprising transistors formed in at least one of the first active region or second active region. <i>See</i> above at Elements 2-3.		
[Claim 1, Element 5] at least a portion of at least one of the first and second active regions having at least one graded dopant concentration to aid carrier movement from the first surface to the second surface of the substrate.	The Western Digital Accused Products include a semiconductor device comprising at least a portion of at least one of the first and second active regions having at least one graded dopant concentration to aid carrier movement from the first surface to the second surface of the substrate. For example, spreading resistance profiling (SRP) analysis shows a graded dopant concentration, as explained below. SRP and SIMS are well-known methods of studying semiconductor devices. See e.g., T. Clarysse, et al. Characterization of electrically active dopant profiles with the spreading resistance probe, Materials Science and Engineering (December 2004). SRP provides an "electrical depth profile" and "gives intrinsically electrical information." Id. at 141, 157. Each SRP data point reflects carrier movement and dopant concentration at the physical location at which it was taken. The plots of SRP data taken from accused products shown herein demonstrate differences in carrier concentration as a function of depth, which generate electric fields within the accused products. That is the SRP plots included in Greenthread's infringement charts evidence both dopant gradients and the corresponding vertical electric drift fields. A silicon sample may be polished at an angle toward the top surface, and a defined profile may be generated over the depth of the sample via the grinding angle. The polished section was then electrically characterized using a		

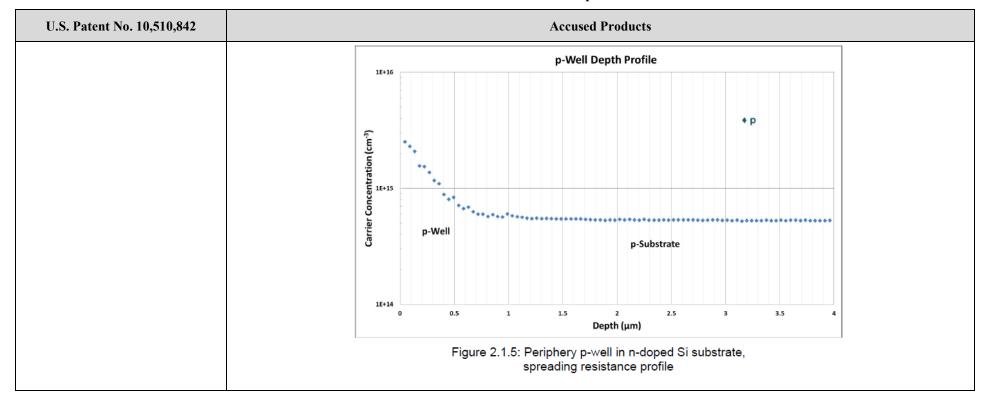
U.S. Patent No. 10,510,842	Accused Pro	oducts
	step prober, which generated a depth profile. For example, the graphs be Western Digital Accused Products, show a graded dopant concentration shown by the concentration corresponding to an n-well in the first graph concentration corresponding to a p-well in the second graph below) to a of the substrate (e.g., downwards, corresponding to increasing depth, in	n (annotated with green oval) in the first active region (e.g., h below) and in the second active region (e.g., as shown by aid carrier movement from the first surface to the second sur
	n-Well De	epth Profile
	1E+17 Out o	• p ■ n p-Substrate
	1E+13 0 0.5 1 1.5	2 2.5 3 3.5 4

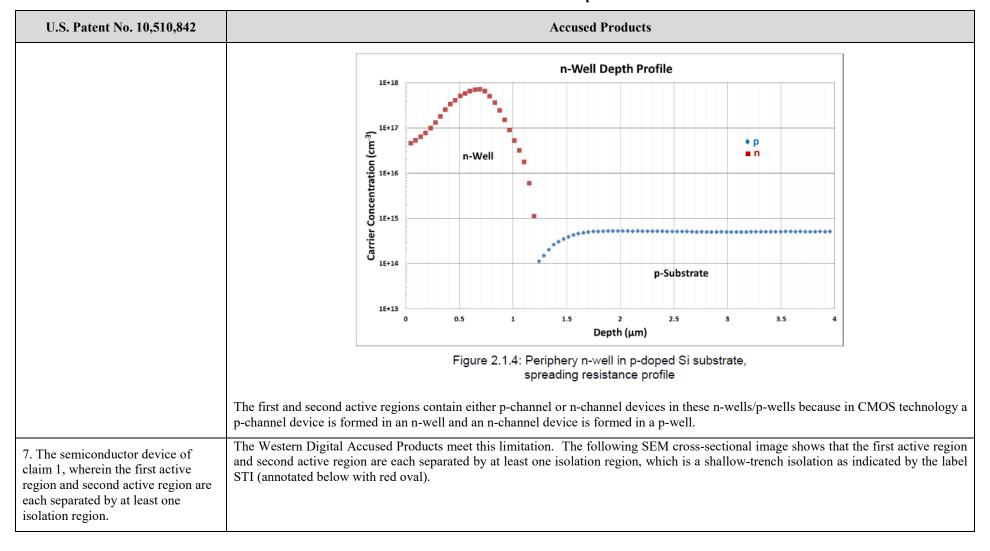






U.S. Patent No. 10,510,842	Accused Products		
	Second active region SID (ne) SID		
	Thus, the first active region and second active region contain one of either p-channel and n-channel devices (e.g., the first active region contains a p-channel device, and the second active region contains an n-channel device).		
6. The semiconductor device of claim 1, wherein the first active region and second active region contain either p-channel or n-channel devices in n-wells or p-wells, respectively, and each well has a graded dopant.	The Western Digital Accused Products meet this limitation. As discussed above for Claim 5, the periphery (region with peripheral NMOS and PMOS transistors shown in Figures 2.3.4 and 2.3.5) contains NMOS (n-channel) and PMOS (p-channel) devices in respective p-wells and n-wells. As discussed above for Claim 1, Elements 2-3 and Claim 5, the p-channel and n-channel devices are contained in the first and active regions (<i>see</i> annotated Figures 2.3.4 and 2.3.5 discussed above). The following graphs obtained via SRP analysis show a p-well having a graded dopant (e.g., depths from 0 to about 0.8 μm in first graph below) and an n-well having a graded dopant (e.g., depths of about 0.7-1.2 μm in second graph below).		

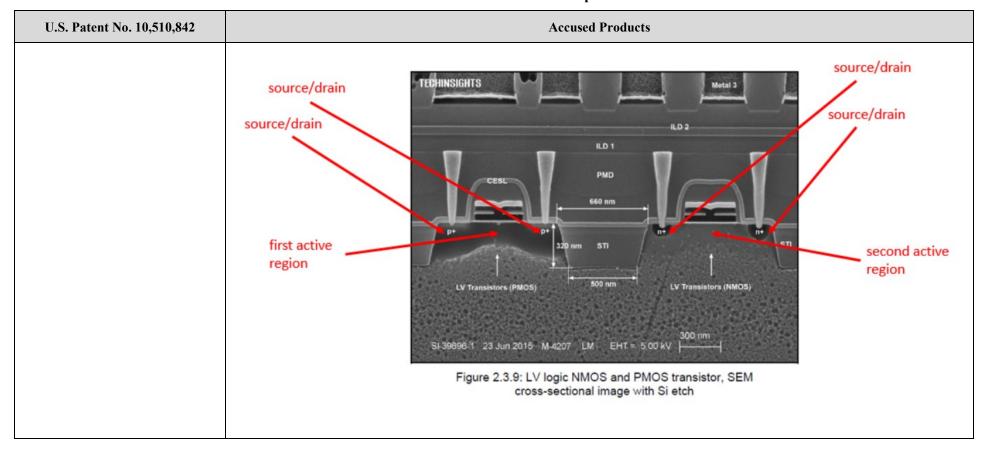




U.S. Patent No. 10,510,842	Accused Products	
	first active region SI-39696-1 23 Jun 2016 M-4207 LM EHT = 500 kV SI-39696-1 23 Jun 2016 M-4207 LM SH Si etch Figure 2.3.9: LV logic NMOS and PMOS transistor, SEM cross-sectional image with Si etch	
8. The semiconductor device of claim 1, wherein the graded dopant is fabricated with an ion implantation process.	Upon information and belief, the graded dopant is fabricated with an ion implantation process. For example, ion implantation is the prevalent process for implementing doping in semiconductor devices, and is believed to be used for the Western Digital Accused Products. Information about the fabrication process for Western Digital Accused Products, including usage of an ion implantation process, is in the possession of the Defendants and is expected to be obtained through discovery.	
[Claim 9, Preamble] A semiconductor device, comprising:	To the extent the preamble is a limitation, the Western Digital Accused Products include a semiconductor device. <i>See</i> above at Claim 1, Preamble.	
[Claim 9, Element 1] a substrate of a first doping type at a first doping level having first and second surfaces;	The Western Digital Accused Products meet this limitation. See above at Claim 1, Element 1.	
[Claim 9, Element 2] a first active region disposed adjacent the first surface of the substrate with a second doping type opposite in	The Western Digital Accused Products meet this limitation. <i>See</i> above at Claim 1, Element 2. Upon information and belief, transistors can be formed in the surface of the first active region. Details regarding formation of transistors are in the possession of the Defendants and are expected to be obtained through discovery.	

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conductivity to the first doping type and within which transistors can be formed in the surface thereof;	
[Claim 9, Element 3] a second active region separate from the first active region disposed adjacent to the first active region and within which transistors can be formed in the surface thereof;	The Western Digital Accused Products meet this limitation. <i>See</i> above at Claim 1, Element 3. Upon information and belief, transistors can be formed in the surface of the second active region. Details regarding formation of transistors are in the possession of the Defendants and are expected to be obtained through discovery.
[Claim 9, Element 4] transistors formed in at least one of the first active region or second active region; and	The Western Digital Accused Products meet this limitation. See above at Claim 1, Element 4.
[Claim 9, Element 5] at least a portion of at least one of the first and second active regions having at least one graded dopant concentration to aid carrier movement from the surface to the substrate.	The Western Digital Accused Products meet this limitation. <i>See</i> above at Claim 1, Element 5 SRP analysis electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Claim 1, Element 5.
10. The semiconductor device of claim 9, wherein the substrate is a ptype substrate.	The Western Digital Accused Products meet this limitation. See above at Claim 2.
12. The semiconductor device of claim 9, wherein the substrate has epitaxial silicon on top of a nonepitaxial substrate.	The Western Digital Accused Products meet this limitation. See above at Claim 4.
13. The semiconductor device of claim 9, wherein the first active region and second active region contain at least one of either p-channel and n-channel devices.	The Western Digital Accused Products meet this limitation. See above at Claim 5.
14. The semiconductor device of claim 9, wherein the first active	The Western Digital Accused Products meet this limitation. See above at Claim 6.

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region and second active region contain either p-channel or n-channel devices in n-wells or p-wells, respectively, and each well has a graded dopant.	
15. The semiconductor device of claim 9, wherein the first active region and second active region are each separated by at least one isolation region.	Upon information and belief, the Western Digital Accused Products meet this limitation. See above at Claim 7.
16. The semiconductor device of claim 9, wherein the graded dopant is fabricated with an ion implantation process.	Upon information and belief, the Western Digital Accused Products meet this limitation. See above at Claim 8.
17. The semiconductor device of claim 1, wherein the first and second active regions are formed adjacent the first surface of the substrate.	The Western Digital Accused Products meet this limitation. See above at Claim 1, Elements 2-3.
18. The semiconductor device of claim 1, wherein the transistors which can be formed in the first and second active regions are CMOS transistors requiring a source, a drain, a gate and a channel region.	The Western Digital Accused Products meet this limitation. <i>See</i> above at Claim 1, Elements 2-3; Claim 6. The SEM images labeled Figures 2.3.5 and 2.3.4 discussed above for Claim 1, Elements 2-3 and Claim 6 show NMOS and PMOS transistors, which are adjacent to one another as shown in the SEM image labeled Figure 2.3.9 discussed above for Claim 1, Element 3. Therefore, the transistors which can be formed in the first and second active regions are CMOS transistors. CMOS transistors require a source, a drain, a gate, and a channel region. The source and drain terminals of transistors are shown below, a gate is between each source-drain pair, and a channel region connects each source to a corresponding drain.

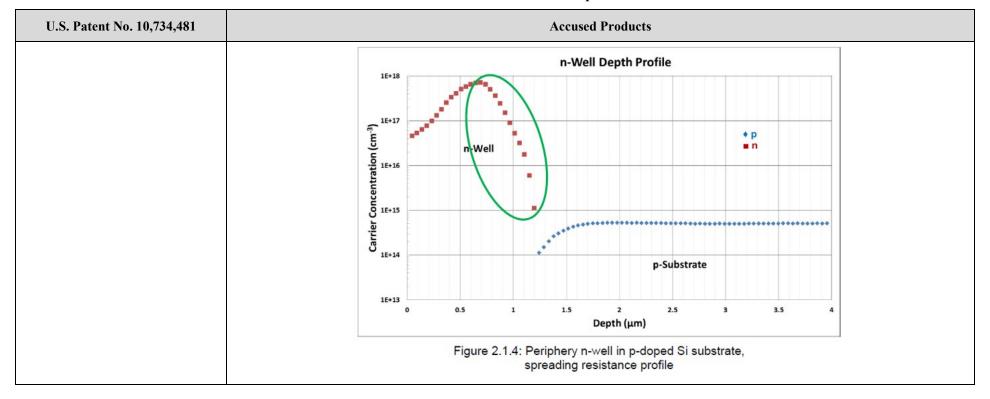


U.S. Patent No. 10,734,481	Accused Products
[Claim 1, Preamble] A semiconductor device, comprising:	To the extent the preamble is a limitation, the Western Digital Accused Products include a semiconductor device. <i>See</i> Exhibit A-1, Claim 1, Preamble. The SanDisk 15 nm 16 GB NAND flash memory referenced in Exhibit A-1 for tear-down analysis is discussed in this claim chart and other infringement contention claim charts as an example of a flash memory representative of the Western Digital Accused Products. Upon information and belief, such a SanDisk flash memory is representative of flash memory devices used in the Western Digital Accused Products for purposes of this claim chart and the other infringement contention claim charts because, e.g., other flash memory devices used in Western Digital Accused Products would have similarly been advantageously designed to move carriers (e.g., towards the substrate) and achieve the performance enhancements described and claimed in the '481 patent (and the other asserted patents). For example, other flash memory devices would similarly have been designed with a dopant gradient in order to improve performance characteristics such as on and off switching times and other performance enhancements described in the Abstract of the '481 patent (and the other asserted patents). Therefore, upon information and belief, other flash memory devices used in Western Digital Accused Products contain similar features as the SanDisk 16 nm 16 GB NAND flash memory, and function in a similar way, with respect to the features claimed in the asserted claims. This claim chart is based on publicly available information, and additional information regarding these and other accused products is expected to be obtained through discovery.
[Claim 1, Element 1] a substrate of a first doping type at a first doping level having first and second surfaces;	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 1.
[Claim 1, Element 2] a first active region disposed adjacent the first surface of the substrate with a second doping type opposite in conductivity to the first doping type and within which transistors can be formed;	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 2.
[Claim 1, Element 3] a second active region separate from the first active region disposed adjacent to the first active region and within which transistors can be formed;	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 3.
[Claim 1, Element 4] transistors formed in at least one of the first active region or second active region;	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 4.

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[Claim 1, Element 5] at least a portion of at least one of the first and second active regions having at least one graded dopant concentration to aid carrier movement from the first surface to the second surface of the substrate; and	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 5 SRP analysis electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.
[Claim 1, Element 6] at least one well region adjacent to the first or second active region containing at least one graded dopant region, the graded dopant region to aid carrier movement from the first surface to the second surface of the substrate.	The Western Digital Accused Products meet this limitation. For example, the SanDisk flash memory includes a p-well (first graph below) and an n-well (second graph below) having graded dopant regions.
	p-Well Depth Profile
	p-Well p-Substrate
	0 0.5 1 1.5 2 2.5 3 3.5 4 Depth (μm)
	Figure 2.1.5: Periphery p-well in n-doped Si substrate, spreading resistance profile

U.S. Patent No. 10,734,481	Accused Products				
	n-Well Depth Profile				
			V		
		n-Wo	ell .	+ p ■ n	
		0 1E+15			
		5 1E+14	*****	***************	•••••
		1E+13		p-Substrate	
		0 0.5	1 15 De	2 2.5 3 3.5 epth (µm)	•
		Figure	e 2.1.4: Periphery n-we spreading resi	ell in p-doped Si substrate, stance profile	
	These graded dopant region Claim 1, Element 5. SRP at				e of the substrate. See Exhibit A-1,
2. The semiconductor device of claim 1, wherein the substrate is a ptype substrate.	The Western Digital Accus	sed Products meet this	s limitation. See Exh	ibit A-1, Claim 2.	
3. The semiconductor device of claim 1, wherein the substrate has epitaxial silicon on top of a nonepitaxial substrate.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 4.				
4. The semiconductor device of claim 1, wherein the first active region and second active region contain one of either p-channel and n-channel devices.	The Western Digital Accus	sed Products meet this	s limitation. See Exh	ibit A-1, Claim 5.	
5. The semiconductor device of claim 1, wherein the first active	The Western Digital Accus	sed Products meet this	s limitation. <i>See</i> Exh	ibit A-1, Claim 6.	

U.S. Patent No. 10,734,481	Accused Products
region and second active region contain either p-channel or n-channel devices in n-wells or p-wells, respectively, and each well has at least one graded dopant.	
6. The semiconductor device of claim 1, wherein the first active region and second active region are each separated by at least one isolation region.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 7.
7. The semiconductor device of claim 1, wherein the graded dopant is fabricated with an ion implantation process.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 8.
8. The semiconductor device of claim 1, wherein the first and second active regions are formed adjacent the first surface of the substrate.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Elements 1-3.
9. The semiconductor device of claim 1, wherein dopants of the graded dopant concentration in the first active region or the second active region are either p-type or n-type.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 5 (SRP analysis of Figures 2.1.4 and 2.1.5 (below) showing n-type doping and p-type doping, respectively, at graded dopant concentration).



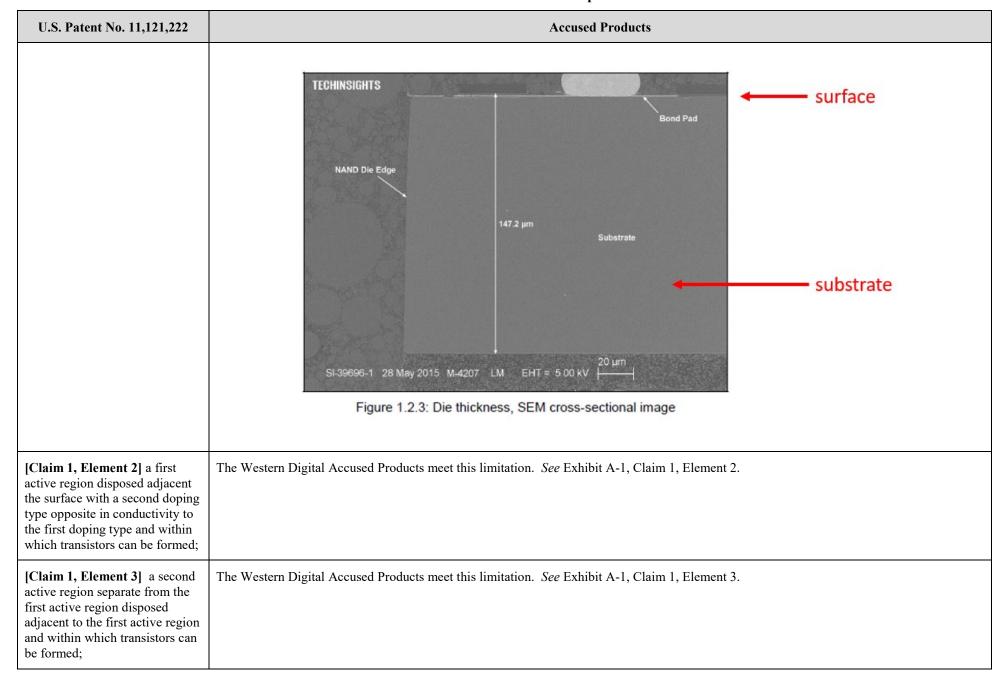
U.S. Patent No. 10,734,481	Accused Products		
	p-Well Depth Profile p-Substrate p-Substrate Figure 2.1.5: Periphery p-well in n-doped Si substrate, spreading resistance profile		
13. The semiconductor device of claim 1, wherein the transistors which can be formed in the first and second active regions are CMOS transistors requiring at least a source, a drain, a gate and a channel.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 18.		
15. The semiconductor device of claim 1, wherein the device is a complementary metal oxide semiconductor (CMOS) with a nonepitaxial substrate.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claims 4 (regarding nonepitaxial substrate), 18 (regarding CMOS).		
16. The semiconductor device of claim 1, wherein the device is a flash memory.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Preamble.		

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[Claim 20, Preamble] A semiconductor device, comprising:	To the extent the preamble is a limitation, the Western Digital Accused Products meet include a semiconductor device. <i>See</i> above at Claim 1, Preamble.
[Claim 20, Element 1] a substrate of a first doping type at a first doping level having first and second surfaces;	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 1.
[Claim 20, Element 2] a first active region disposed adjacent the first surface of the substrate with a second doping type opposite in conductivity to the first doping type and within which transistors can be formed in the surface thereof;	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 9, Element 2.
[Claim 20, Element 3] a second active region separate from the first active region disposed adjacent to the first active region and within which transistors can be formed in the surface thereof;	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 9, Element 3.
[Claim 20, Element 4] transistors formed in at least one of the first active region or second active region;	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 4.
[Claim 20, Element 5] at least a portion of at least one of the first and second active regions having at least one graded dopant concentration to aid carrier movement from the surface to the substrate; and	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 5. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.
[Claim 20, Element 6] at least one well region adjacent to the first or second active region containing at least one graded dopant region, the graded dopant region to aid carrier	The Western Digital Accused Products meet this limitation. <i>See</i> above at Claim 1, Element 6. <i>See also</i> SRP analysis reproduced at Exhibit A-1 Claim 1 Element 5 electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.

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movement from the first surface to the second surface of the substrate.	
22. The semiconductor device of claim 20, wherein the substrate is a p-type substrate.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 2.
23. The semiconductor device of claim 20, wherein the substrate has epitaxial silicon on top of a nonepitaxial substrate.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 4.
24. The semiconductor device of claim 20, wherein the first active region and second active region contain at least one of either p-channel and n-channel devices.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 5.
25. The semiconductor device of claim 20, wherein the first active region and second active region contain either p-channel or n-channel devices in n-wells or p-wells, respectively, and each well has at least one graded dopant.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 6.
26. The semiconductor device of claim 20, wherein the first active region and second active region are each separated by at least one isolation region.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 7.
27. The semiconductor device of claim 20, wherein dopants of the graded dopant concentration in the first active region or the second active region are either p-type or n-type.	The Western Digital Accused Products meet this limitation. See above at Claim 9.

U.S. Patent No. 10,734,481	Accused Products
31. The semiconductor device of claim 20, wherein the graded dopant is fabricated with an ion implantation process.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 8.
32. The semiconductor device of claim 20, wherein the substrate is a complementary metal oxide semiconductor (CMOS) device.	The Western Digital Accused Products meet this limitation. See above at Claim 15.
33. The semiconductor device of claim 20, wherein the device is a flash memory.	The Western Digital Accused Products meet this limitation. See above at Claim 16.

U.S. Patent No. 11,121,222	Accused Products
[Claim 1, Preamble] A VLSI semiconductor device, comprising:	To the extent the preamble is a limitation, the Western Digital Accused Products include a VLSI semiconductor device. The SanDisk flash memory discussed for claim 1 of Exhibit A-1 is a semiconductor device (<i>see</i> Exhibit A-1, Claim 1, Preamble) with millions of transistors, and is a VLSI semiconductor device upon information and belief. Details regarding transistor count are in the possession of the Defendants and are expected to be obtained through discovery.
	The SanDisk 15 nm 16 GB NAND flash memory referenced in Exhibit A-1 is discussed in this claim chart and other infringement contention claim charts as an example of a flash memory representative of the Western Digital Accused Products. Upon information and belief, such a SanDisk flash memory is representative of flash memory devices used in the Western Digital Accused Products for purposes of this claim chart and the other infringement contention claim charts because, e.g., other flash memory devices used in Western Digital Accused Products would have similarly been advantageously designed to move carriers (e.g., towards the substrate) and achieve the performance enhancements described and claimed in the '222 patent (and the other asserted patents). For example, other flash memory devices would similarly have been designed with a dopant gradient in order to improve performance characteristics such as on and off switching times and other performance enhancements described in the Abstract of the '222 patent (and the other asserted patents). Therefore, upon information and belief, other flash memory devices used in Western Digital Accused Products contain similar features as the SanDisk 15 nm 16 GB NAND flash memory, and function in a similar way with respect to the features claimed in the asserted claims.
	This claim chart is based on publicly available information, and additional information regarding these and other accused products is expected to be obtained through discovery.
[Claim 1, Element 1] a substrate of a first doping type at a first doping level having a surface;	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 1.



U.S. Patent No. 11,121,222	Accused Products
[Claim 1, Element 4] transistors formed in at least one of the first active region or second active region;	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 4.
[Claim 1, Element 5] at least a portion of at least one of the first and second active regions having at least one graded dopant concentration to aid carrier movement from the first and second active regions towards an area of the substrate where there are no active regions; and	The Western Digital Accused Products meet this limitation. <i>See</i> Exhibit A-1, Claim 1, Element 5. For example, referencing the SRP graph discussed at Exhibit A-1, Claim 1, Element 5, there are no active regions at depths of about 1.3 µm and greater. <i>See also</i> SRP analysis reproduced at Exhibit A-1, Claim 1, Element 5 electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.
[Claim 1, Element 6] at least one well region adjacent to the first or second active region containing at least one graded dopant region, the graded dopant region to aid carrier movement from the surface towards the area of the substrate where there are no active regions, wherein at least some of the transistors form digital logic of the VLSI semiconductor device.	The Western Digital Accused Products meet this limitation. See Exhibit A-2, Claim 1, Element 6. Upon information and belief, at least some of the transistors form digital logic of the VLSI semiconductor device. For example, transistors are commonly used to implement digital logic, e.g., for controlling access to memory components/functionality. Details regarding transistors in the Western Digital Accused Products are in the possession of the Defendants and are expected to be obtained through discovery. See also SRP analysis reproduced at Exhibit A-1, Claim 1, Element 5 electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.
2. The VLSI semiconductor device of claim 1, wherein the substrate is a p-type substrate.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 2.
3. The VLSI semiconductor device of claim 1, wherein the substrate has epitaxial silicon on top of a nonepitaxial substrate.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 4.
4. The VLSI semiconductor device of claim 1, wherein the first active region and second	The Western Digital Accused Products meet this limitation. <i>See</i> Exhibit A-1, Claim 5; Exhibit A-2, Claim 4. Upon information and belief, the first and second active regions contain digital logic as claimed. <i>See</i> above at Claim 1, Element 6.

U.S. Patent No. 11,121,222	Accused Products
active region contain digital logic formed by one of either p-channel and n-channel devices.	
5. The VLSI semiconductor device of claim 1, wherein the first active region and second active region contain either p-channel or n-channel devices in n-wells or p-wells, respectively, and each well has at least one graded dopant.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 6.
6. The VLSI semiconductor device of claim 1, wherein the first active region and second active region are each separated by at least one isolation region.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 7.
7. The VLSI semiconductor device of claim 1, wherein the graded dopant is fabricated with an ion implantation process.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 8.
8. The VLSI semiconductor device of claim 1, wherein the first and second active regions are formed adjacent the first surface of the substrate.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Elements 1-3.
9. The VLSI semiconductor device of claim 1, wherein dopants of the graded dopant concentration in the first active region or the second active region are either p-type or n-type.	The Western Digital Accused Products meet this limitation. See Exhibit A-2, Claim 9.
13. The VLSI semiconductor device of claim 1, wherein the	The Western Digital Accused Products meet this limitation. <i>See</i> Exhibit A-2, Claim 13. Upon information and belief, the transistors which can be formed in the first and second active regions are CMOS digital logic transistors as claimed. <i>See</i> above at Claim 1, Element 6.

U.S. Patent No. 11,121,222	Accused Products
transistors which can be formed in the first and second active regions are CMOS digital logic transistors requiring at least a source, a drain, a gate and a channel.	
15. The VLSI semiconductor device of claim 1, wherein the device is a complementary metal oxide semiconductor (CMOS) with a nonepitaxial substrate.	The Western Digital Accused Products meet this limitation. See Exhibit A-2, Claim 15.
16. The VLSI semiconductor device of claim 1, wherein the device is a flash memory.	The Western Digital Accused Products meet this limitation. See Exhibit A-2, Claim 16.
17. The VLSI semiconductor device of claim 1, wherein the device comprises digital logic and capacitors.	The Western Digital Accused Products meet this limitation. Upon information and belief, the semiconductor device comprises digital logic and capacitors. <i>See</i> above at Claim 1, Element 6 (discussion regarding digital logic). Details regarding digital logic and capacitors in the Western Digital Accused Products are in the possession of the Defendants and are expected to be obtained through discovery.
20. The VLSI semiconductor device of claim 1, wherein each of the first and second active regions are in the lateral or vertical direction.	The Western Digital Accused Products meet this limitation. As shown by SEM imaging (see Exhibit A-1, Claim 1, Elements 1-3), each of the first and second active regions are in the lateral or vertical direction.
[Claim 21, Preamble] A VLSI semiconductor device, comprising:	To the extent the preamble is a limitation, the Western Digital Accused Products include a semiconductor device. <i>See</i> above at Claim 1, Preamble.
[Claim 21, Element 1] a substrate of a first doping type at a first doping level having a surface;	The Western Digital Accused Products meet this limitation. See above at Claim 1, Element 1.
[Claim 21, Element 2] a first active region disposed adjacent the surface of the substrate with a second doping type opposite in	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 9, Element 2.

U.S. Patent No. 11,121,222	Accused Products
conductivity to the first doping type and within which transistors can be formed in the surface thereof;	
[Claim 21, Element 3] a second active region separate from the first active region disposed adjacent to the first active region and within which transistors can be formed in the surface thereof;	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 9, Element 3.
[Claim 21, Element 4] transistors formed in at least one of the first active region or second active region;	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 4.
[Claim 21, Element 5] at least a portion of at least one of the first and second active regions having at least one graded dopant concentration to aid carrier movement from the surface to an area of the substrate where there are no active regions; and	The Western Digital Accused Products meet this limitation. See above at Claim 1, Element 5. See also SRP analysis reproduced at Exhibit A-1, Claim 1, Element 5 electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.
[Claim 21, Element 6] at least one well region adjacent to the first or second active region containing at least one graded dopant region, the graded dopant region to aid carrier movement from the surface to the area of the substrate where there are no active regions, and wherein the graded dopant concentration is linear, quasilinear, error function, complementary error function, or any combination thereof.	The Western Digital Accused Products meet this limitation. See Exhibit A-2, Claim 1, Element 6. As shown by SRP analysis (see Exhibit A-1, Claim 1, Element 1), the graded dopant concentration is linear, quasilinear, error function, complementary error function, or any combination thereof. For example, the quasilinear nature of the concentration is shown in the SRP graph discussed at Exhibit A-1, Claim 1, Element 5. See also SRP analysis reproduced at Exhibit A-1, Claim 1, Element 5 electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.

U.S. Patent No. 11,121,222	Accused Products
23. The VLSI semiconductor device of claim 21, wherein the substrate is a p-type substrate.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 2.
24. The VLSI semiconductor device of claim 21, wherein the substrate has epitaxial silicon on top of a nonepitaxial substrate.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 4.
25. The VLSI semiconductor device of claim 21, wherein the first active region and second active region contain at least one of either p-channel and n-channel devices.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 5.
26. The VLSI semiconductor device of claim 21, wherein the first active region and second active region contain either p-channel or n-channel devices in n-wells or p-wells, respectively, and each well has at least one graded dopant.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 6.
27. The VLSI semiconductor device of claim 21, wherein the first active region and second active region are each separated by at least one isolation region.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 7.
28. The VLSI semiconductor device of claim 21, wherein dopants of the graded dopant concentration in the first active region or the second active region are either p-type or n-type.	The Western Digital Accused Products meet this limitation. See Exhibit A-2, Claim 9.
32. The VLSI semiconductor device of claim 21, wherein the	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 8.

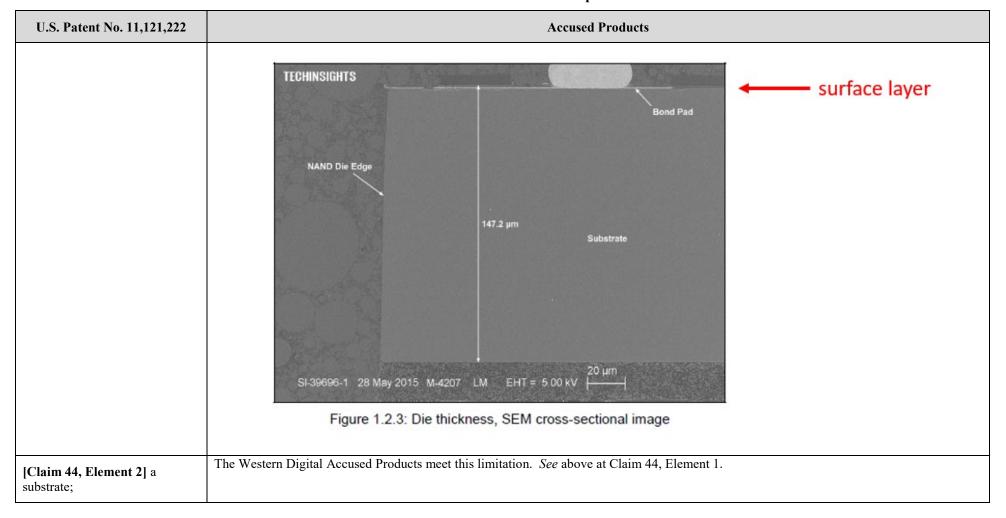
U.S. Patent No. 11,121,222	Accused Products
graded dopant is fabricated with an ion implantation process.	
33. The VLSI semiconductor device of claim 21, wherein the substrate is a complementary metal oxide semiconductor (CMOS) device.	The Western Digital Accused Products meet this limitation. See Exhibit A-2, Claim 15.
34. The VLSI semiconductor device of claim 21, wherein the device is a flash memory.	The Western Digital Accused Products meet this limitation. See Exhibit A-2, Claim 16.
38. The VLSI semiconductor device of claim 21, wherein each of the first and second active regions are in the lateral or vertical direction.	first active region Figure 2.3.9: LV Transistors (PMOS) Figure 2.3.9: LV logic NMOS and PMOS transistor, SEM cross-sectional image with Si etch

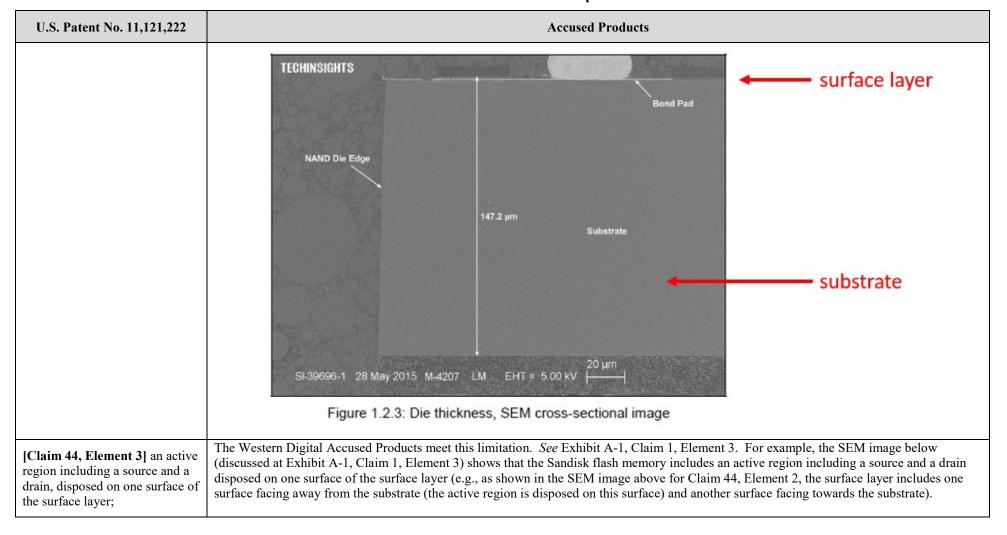
U.S. Patent No. 11,121,222	Accused Products
[Claim 39, Preamble] A semiconductor device, comprising:	To the extent the preamble is a limitation, the Western Digital Accused Products include a semiconductor device. See Exhibit A-1, Claim 1, Preamble.
[Claim 39, Element 1] a substrate of a first doping type at a first doping level;	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 1.
[Claim 39, Element 2] a first active region disposed adjacent to a surface of the substrate with a second doping type opposite in conductivity to the first doping type and within which transistors can be formed;	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 2.
[Claim 39, Element 3] a second active region separate from the first active region disposed adjacent to the first active region and within which transistors can be formed;	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 3.
[Claim 39, Element 4] transistors formed in at least one of the first active region or second active region; and	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 4.
[Claim 39, Element 5] at least a portion of at least one of the first and second active regions having at least one graded dopant concentration to aid carrier movement from the first or second active region to at least one substrate area where there is no active region.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 5; see above at Claim 21, Element 5. See also SRP analysis reproduced at Exhibit A-1, Claim 1, Element 5 electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.
40. The semiconductor device of claim 39 further comprising at least one well region adjacent to	The Western Digital Accused Products meet this limitation. <i>See</i> Exhibit A-2, Claim 1, Element 6. <i>See also</i> SRP analysis reproduced at Exhibit A-1, Claim 1, Element 5 electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.

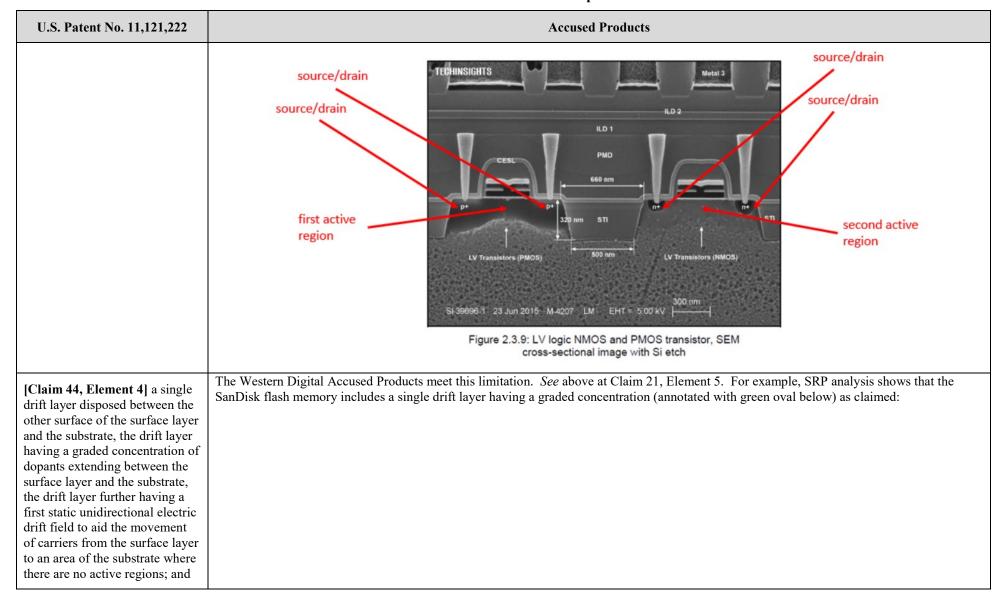
U.S. Patent No. 11,121,222	Accused Products
the first or second active region and containing at least one graded dopant region, the graded dopant region to aid carrier movement from any region in the well to the substrate area where there is no well.	
[Claim 41, Preamble] A semiconductor device, comprising:	To the extent the preamble is a limitation, the Western Digital Accused Products include a semiconductor device. <i>See</i> above at Claim 39, Preamble.
[Claim 41, Element 1] a substrate of a first doping type at a first doping level;	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 1.
[Claim 41, Element 2] a first active region disposed adjacent to a surface of the substrate with a second doping type opposite in conductivity to the first doping type and within which transistors can be formed;	The Western Digital Accused Products meet this limitation. See above at Claim 39, Element 2.
[Claim 41, Element 3] a second active region separate from the first active region disposed adjacent to the first active region and within which transistors can be formed;	The Western Digital Accused Products meet this limitation. See above at Claim 39, Element 3.
[Claim 41, Element 4] transistors formed in at least one of the first active region or second active region; and	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 4.
[Claim 41, Element 5] at least a portion of at least one of the first and second active regions having at least one graded dopant acceptor concentration to aid	The Western Digital Accused Products meet this limitation. <i>See</i> above at Claim 21, Element 5. The following graph obtained via SRP analysis reveals at least one graded dopant acceptor concentration (e.g., concentration in p-well) as claimed.

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carrier movement from the first or second active region to at least one substrate area where there is no active region.	P-Well Depth Profile p-Well Depth Profile p-Substrate p-Substrate p-Substrate p-Substrate p-Substrate See also SRP analysis reproduced at Exhibit A-1, Claim 1, Element 5 electrically characterizing the accused product and showing carrier
[Claim 42, Preamble] A semiconductor device, comprising:	movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5. To the extent the preamble is a limitation, the Western Digital Accused Products include a semiconductor device. See above at Claim 39, Preamble.
[Claim 42, Element 1] a substrate of a first doping type at a first doping level;	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 1.
[Claim 42, Element 2] a first active region disposed adjacent to a surface of the substrate with a second doping type opposite in conductivity to the first doping type and within which transistors can be formed;	The Western Digital Accused Products meet this limitation. See above at Claim 39, Element 2.
[Claim 42, Element 3] a second active region separate from the first active region	The Western Digital Accused Products meet this limitation. See above at Claim 39, Element 3.

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disposed adjacent to the first active region and within which transistors can be formed;	
[Claim 42, Element 4] transistors formed in at least one of the first active region or second active region; and	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Element 4.
[Claim 42, Element 5] at least a portion of at least one of the first and second active regions having at least one graded donor dopant concentration to aid carrier movement from the first or second active region to at least one substrate area where there is no active region.	The Western Digital Accused Products meet this limitation. SRP analysis (see Exhibit A-1, Claim 1, Element 5) reveals at least one graded dopant acceptor concentration (e.g., concentration in n-well) as claimed. See also SRP analysis reproduced at Exhibit A-1, Claim 1, Element 5 electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.
[Claim 44, Preamble] A CMOS Semiconductor device comprising:	To the extent the preamble is a limitation, the Western Digital Accused Products include a CMOS Semiconductor device. <i>See</i> Exhibit A-1, Claim 1, Preamble; Exhibit A-1, Claim 18.
[Claim 44, Element 1]: a surface layer;	The Western Digital Accused Products meet this limitation. See above at Claim 21, Element 1.







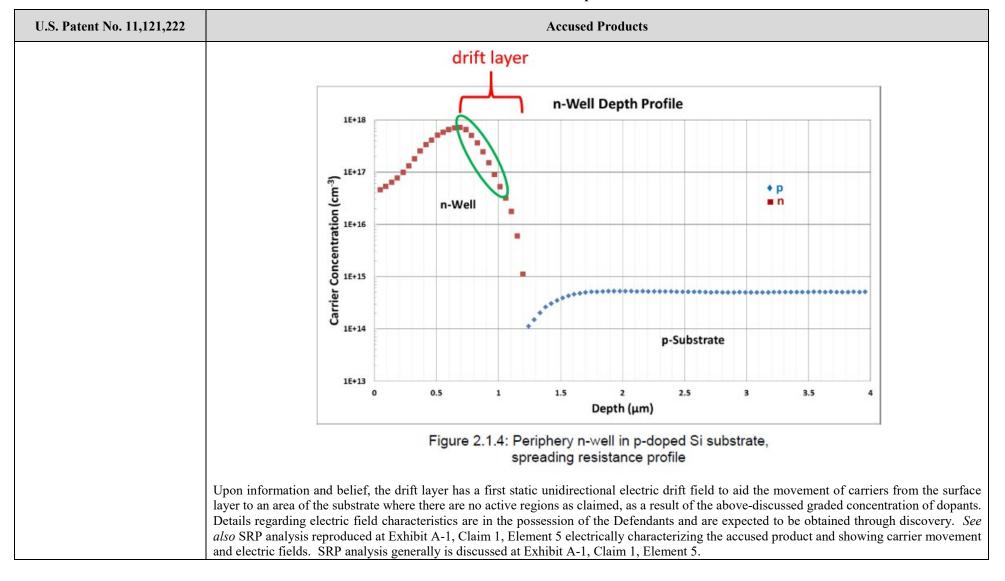


Exhibit A-3 to Greenthread's Complaint

U.S. Patent No. 11,121,222

[Claim 44, Element 5] at least one well region disposed in the single drift layer, the well region having a graded concentration of dopants and a second static unidirectional electric drift field to aid the movement of carriers from the surface layer to the area of the substrate where there are no active regions.

Accused Products

The Western Digital Accused Products meet this limitation. See above at Claim 21, Element 6. The well region (discussed above for Claim 21, Element 6) has a graded concentration of dopants (annotated with purple oval below to indicate a region of relatively steeper slope in concentration, compared to the shallower region discussed for Claim 44, Element 4).

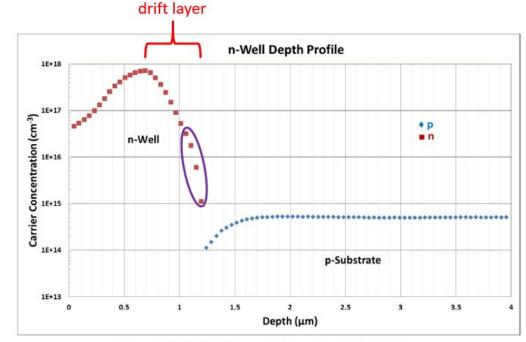


Figure 2.1.4: Periphery n-well in p-doped Si substrate, spreading resistance profile

Upon information and belief, the well region is disposed in the single drift layer, and it has a second static unidirectional electric drift field to aid the movement of carriers from the surface layer to the area of the substrate where there are no active regions as claimed, as a result of the well region's graded concentration of dopants. Details regarding electric field characteristics are in the possession of the Defendants and are expected to be obtained through discovery. See also SRP analysis reproduced at Exhibit A-1, Claim 1, Element 5 electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.

U.S. Patent No. 8,421,195	Accused Products
[Claim 1, Preamble] A CMOS Semiconductor device comprising:	To the extent the preamble is a limitation, the Western Digital Accused Products include a CMOS semiconductor device. <i>See</i> Exhibit A-3, Claim 44, Preamble. The SanDisk 15 nm 16 GB NAND flash memory referenced in Exhibit A-1 is discussed in this claim chart and other infringement contention claim charts as an example of a flash memory representative of the Western Digital Accused Products. Upon information and belief, such a SanDisk flash memory is representative of flash memory devices used in the Western Digital Accused Products for purposes of this claim chart and the other infringement contention claim charts because, e.g., other flash memory devices used in Western Digital Accused Products would have similarly been advantageously designed to move carriers (e.g., towards the substrate) and achieve the performance enhancements described and claimed in the '195 patent (and the other asserted patents). For example, other flash memory devices would similarly have been designed with a dopant gradient in order to improve performance characteristics such as on and off switching times and other performance enhancements described in the Abstract of the '195 patent (and the other asserted patents). Therefore, upon information and belief, other flash memory devices used in Western Digital Accused Products contain similar features as the SanDisk 15 nm 16 GB NAND flash memory, and function in a similar way with respect to the features claimed in the asserted claims. This claim chart is based on publicly available information, and additional information regarding these and other accused products is expected to be obtained through discovery.
[Claim 1, Element 1] a surface layer;	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 44, Element 1.
[Claim 1, Element 2] a substrate;	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 44, Element 2.
[Claim 1, Element 3] an active region including a source and a drain, disposed on one surface of said surface layer;	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 44, Element 3.
[Claim 1, Element 4] a single drift layer disposed between the other surface of said surface layer and said substrate, said drift layer having a graded concentration of dopants extending between said surface layer and said substrate, said drift layer further having a first static unidirectional electric drift field to aid the movement of minority carriers from said surface layer to said substrate; and	The Western Digital Accused Products meet this limitation. <i>See</i> Exhibit A-3, Claim 44, Element 4. Upon information and belief, the drift layer (<i>see</i> Exhibit A-3, Claim 44, Element 4) has a first static unidirectional electric drift field to aid the movement of minority carriers from the surface layer to the substrate, as claimed. Details regarding electric field characteristics are in the possession of the Defendants and are expected to be obtained through discovery. <i>See also</i> SRP analysis reproduced at Exhibit A-1, Claim 1, Element 5 electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.
[Claim 1, Element 5] at least one well region disposed in said single	The Western Digital Accused Products meet this limitation. <i>See</i> Exhibit A-3, Claim 44, Element 5. Upon information and belief, the well region has a second static unidirectional electric drift field to aid the movement of minority carriers from the surface layer to the substrate, as claimed. Details regarding electric field characteristics are in the possession of the Defendants and are expected to be obtained through

U.S. Patent No. 8,421,195	Accused Products
drift layer, said well region having a graded concentration of dopants and a second static unidirectional electric drift field to aid the movement of minority carriers from said surface layer to said substrate.	discovery. See also SRP analysis reproduced at Exhibit A-1, Claim 1, Element 5 electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.
2. The CMOS Semiconductor device of claim 1, wherein the said drift layer is a deeply-implanted layer.	The Western Digital Accused Products meet this limitation. Upon information and belief, the drift layer is a deeply-implanted layer.
3. The CMOS Semiconductor device of claim 1, wherein said drift layer is an epitaxial layer.	The Western Digital Accused Products meet this limitation. <i>See</i> Exhibit A-1, Claim 4; Exhibit A-3, Claim 44, Element 4. Upon information and belief, the drift layer is grown above the substrate and is an epitaxial layer.
5. The CMOS Semiconductor device of claim 1, wherein said graded concentration follows a quasi-linear gradient.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Elements 1, 5.
6. The CMOS Semiconductor device of claim 1, wherein said graded concentration follows an exponential gradient.	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Elements 1, 5.

U.S. Patent No. 9,190,502	Accused Products
[Claim 7, Preamble] A semiconductor device comprising:	To the extent the preamble is a limitation, the Western Digital Accused Products include a semiconductor device. <i>See</i> Exhibit A-4, Claim 1, Preamble. The SanDisk 15 nm 16 GB NAND flash memory referenced in Exhibit A-1 is discussed in this claim chart and other infringement contention claim charts as an example of a flash memory representative of the Western Digital Accused Products. Upon information and belief, such a SanDisk flash memory is representative of flash memory devices used in the Western Digital Accused Products for purposes of this claim chart and the other infringement contention claim charts because, e.g., other flash memory devices used in Western Digital Accused Products would have similarly been advantageously designed to move carriers (e.g., towards the substrate) and achieve the performance enhancements described and claimed in the '502 patent (and the other asserted patents). For example, other flash memory devices would similarly have been designed with a dopant gradient in order to improve performance characteristics such as on and off switching times and other performance enhancements described in the Abstract of the '502 patent (and the other asserted patents). Therefore, upon information and belief, other flash memory devices used in Western Digital Accused Products contain similar features as the SanDisk 15 nm 16 GB NAND flash memory, and function in a similar way with respect to the features claimed in the asserted claims. This claim chart is based on publicly available information, and additional information regarding these and other accused products is expected to be obtained through discovery.
[Claim 7, Element 1] a surface layer;	The Western Digital Accused Products meet this limitation. See Exhibit A-4, Claim 1, Element 1.
[Claim 7, Element 2] a substrate;	The Western Digital Accused Products meet this limitation. See Exhibit A-4, Claim 1, Element 2.
[Claim 7, Element 3] an active region including a source and a drain, disposed on one surface of said surface layer;	The Western Digital Accused Products meet this limitation. See Exhibit A-4, Claim 1, Element 3.
[Claim 7, Element 4] a single drift layer disposed between the other surface of said surface layer and said substrate, said drift layer having a graded concentration of dopants generating a first static unidirectional electric drift field to aid the movement of minority carriers from said surface layer to said substrate;	The Western Digital Accused Products meet this limitation. <i>See</i> Exhibit A-4, Claim 1, Element 4. The graded concentration of dopants observed via SRP analysis (<i>see</i> Exhibit A-1, Claim 1, Elements 1, 5) generates a first static unidirectional electric drift field to aid the movement of minority carriers, as claimed. <i>See also</i> SRP analysis reproduced at Exhibit A-1, Claim 1, Element 5 electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.
[Claim 7, Element 5] and at least one well region disposed in said single drift layer, said well region having a graded concentration of	The Western Digital Accused Products meet this limitation. <i>See</i> Exhibit A-4, Claim 1, Element 5. <i>See also</i> SRP analysis reproduced at Exhibit A-1, Claim 1, Element 5 electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.

U.S. Patent No. 9,190,502	Accused Products
dopants generating a second static unidirectional electric drift field to aid the movement of minority carriers from said surface layer to said substrate.	
8. The semiconductor device of claim 7 wherein said first and second static unidirectional electric fields are adapted to respective grading of dopants to aid movements of carriers in respective active regions.	The Western Digital Accused Products meet this limitation. Upon information and belief, the first and second static unidirectional electric fields are adapted to respective grading of dopants to aid movements of carriers in respective active regions. Details regarding the electric fields and active regions are in the possession of the Defendants and are expected to be obtained through discovery. <i>See also</i> SRP analysis reproduced at Exhibit A-1, Claim 1, Element 5 electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.
11. The semiconductor device of claim 7 wherein the semiconductor device is a flash memory device.	The Western Digital Accused Products meet this limitation. See Exhibit A-2, Claim 16.

U.S. Patent No. 11,316,014	Accused Products
[Claim 1, Preamble] An electronic system, the system comprising:	To the extent the preamble is a limitation, the Western Digital Accused Products include an electronic system. <i>See</i> Exhibit A-1, Claim 1, Preamble; Exhibit A-4, Claim 1, Preamble. Each Western Digital Accused Product is an electronic system, because a computer is an electronic system.
	The SanDisk 15 nm 16 GB NAND flash memory referenced in Exhibit A-1 is discussed in this claim chart and other infringement contention claim charts as an example of a flash memory representative of the Western Digital Accused Products. Upon information and belief, such a SanDisk flash memory is representative of flash memory devices used in the Western Digital Accused Products for purposes of this claim chart and the other infringement contention claim charts because, e.g., other flash memory devices used in Western Digital Accused Products would have similarly been advantageously designed to move carriers (e.g., towards the substrate) and achieve the performance enhancements described and claimed in the '014 patent (and the other asserted patents). For example, other flash memory devices would similarly have been designed with a dopant gradient in order to improve performance characteristics such as on and off switching times and other performance enhancements described in the Abstract of the '014 patent (and the other asserted patents). Therefore, upon information and belief, other flash memory devices used in Western Digital Accused Products contain similar features as the SanDisk 15 nm 16 GB NAND flash memory, and function in a similar way with respect to the features claimed in the asserted claims.
	This claim chart is based on publicly available information, and additional information regarding these and other accused products is expected to be obtained through discovery.
[Claim 1, Element 1a] at least one semiconductor device, the at least one semiconductor device including:	The Western Digital Accused Products meet this limitation. See Exhibit A-1, Claim 1, Preamble.
[Claim 1, Element 1b] a substrate of a first doping type at a first doping level having a surface;	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 1, Element 1.
[Claim 1, Element 1c] a first active region disposed adjacent the surface with a second doping type opposite in conductivity to the first doping type and within which transistors can be formed;	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 1, Element 2; Exhibit A-1, Claim 9, Element 2.
[Claim 1, Element 1d] a second active region separate from the first active region disposed adjacent to the first active region and within	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 1, Element 3; Exhibit A-1, Claim 9, Element 3.
which transistors can be formed; [Claim 1, Element 1e] transistors formed in at least one of the first active region or second active region;	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 1, Element 4.

U.S. Patent No. 11,316,014	Accused Products
[Claim 1, Element 1f] at least a portion of at least one of the first and second active regions having at least one graded dopant concentration to aid carrier movement from the first and second active regions towards an area of the substrate where there are no active regions; and	The Western Digital Accused Products meet this limitation. <i>See</i> Exhibit A-3, Claim 1, Element 5. <i>See also</i> SRP analysis reproduced at Exhibit A-1, Claim 1, Element 5 electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.
[Claim 1, Element 1g] at least one well region adjacent to the first or second active region containing at least one graded dopant region, the graded dopant region to aid carrier movement from the surface towards the area of the substrate where there are no active regions, wherein at least some of the transistors form digital logic of the semiconductor device.	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 1, Element 6; Exhibit A-3, Claim 21, Element 6. See also SRP analysis reproduced at Exhibit A-1, Claim 1, Element 5 electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.
2. The system of Claim 1, wherein the substrate of the at least one semiconductor device is a p-type substrate.	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 2.
3. The system of Claim 1, wherein the substrate of the at least one semiconductor device has epitaxial silicon on top of a nonepitaxial substrate.	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 3.
4. The system of Claim 1, wherein the first active region and second active region of the at least one semiconductor device contain digital logic formed by one of either p-channel and n-channel devices.	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 4.
5. The system of Claim 1, wherein the first active region and second active region of the at least one semiconductor device contain either p-channel or n-channel	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 5.

U.S. Patent No. 11,316,014	Accused Products
devices in n-wells or p-wells,	
respectively, and each well has at	
least one graded dopant.	
6. The system of Claim 1, wherein	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 6.
the first active region and second	The Western Digital Accused Products meet this minitation. See Exhibit A-5, Claim 6.
active region of the at least one	
semiconductor device are each	
separated by at least one isolation	
region.	
7. The system of Claim 1, wherein	The Water Divid According to the desired of the Projection of the
the graded dopant is fabricated with	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 7.
an ion implantation process.	
8. The system of Claim 1, wherein	The Water Divid According to the divided on C. E. Lily A. 2. Chin 0.
the first and second active regions of	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 8.
the at least one semiconductor	
device are formed adjacent the first	
surface of the substrate of	
the at least one semiconductor	
device.	
9. The system of Claim 1, wherein	The Water Divid According to the desired of the Table A 2 Chine 0
dopants of the graded dopant	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 9.
concentration in the first active	
region or the second active region of	
the at least one semiconductor	
device are either p-type or n-type.	
13. The system of claim 1, wherein	The Water Divid According to the divided of the Table A 2 Chine 12
the transistors which can be formed	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 13.
in the first and second active regions	
of the at least one semiconductor	
device are CMOS digital logic	
transistors requiring at least a	
source, a drain, a gate and a channel.	
15. The system of Claim 1, wherein	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 15.
the at least one semiconductor	The Western Digital Accused Floducts meet this inintation. See Exhibit A-5, Claim 15.
device is a complementary metal	
oxide semiconductor (CMOS) with	
a nonepitaxial substrate.	
16. The system of Claim 1, wherein	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 16.
the at least one semiconductor	The Western Digital Accused Floudets nicel this inintation. See Exhibit A-3, Claim 10.
device is a flash memory.	

U.S. Patent No. 11,316,014	Accused Products
17. The system of Claim 1, wherein the at least one semiconductor device comprises digital logic and capacitors.	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 17.
20. The system of Claim 1, wherein each of the first and second active regions of the at least one semiconductor device are in the lateral or vertical direction.	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 20.
[Claim 21, Preamble] An electronic system, the system comprising:	To the extent the preamble is a limitation, the Western Digital Accused Products include an electronic system. <i>See</i> above at Claim 1, Preamble.
[Claim 21, Element 1a] at least one semiconductor device, the at least one semiconductor device including:	The Western Digital Accused Products meet this limitation. See above at Claim 1, Element 1a.
[Claim 21, Element 1b] a substrate of a first doping type at a first doping level having a surface;	The Western Digital Accused Products meet this limitation. See above at Claim 1, Element 1b.
[Claim 21, Element 1c] a first active region disposed adjacent the surface of the substrate with a second doping type opposite in conductivity to the first doping type and within which transistors can be formed in the surface thereof;	The Western Digital Accused Products meet this limitation. See above at Claim 1, Element 1c; Exhibit A-1, Claim 9, Element 2.
[Claim 21, Element 1d] a second active region separate from the first active region disposed adjacent to the first active region and within which transistors can be formed in the surface thereof;	The Western Digital Accused Products meet this limitation. See above at Claim 1, Element 1d; Exhibit A-1, Claim 9, Element 3.
[Claim 21, Element 1e] transistors formed in at least one of the first active region or second active region;	The Western Digital Accused Products meet this limitation. See above at Claim 1, Element 1e.
[Claim 21, Element 1f] at least a portion of at least one of the first and second active regions having at least one graded dopant concentration to aid carrier movement from the surface to an	The Western Digital Accused Products meet this limitation. <i>See</i> above at Claim 1, Element 1f; Exhibit A-1, Claim 9, Element 5. <i>See also</i> SRP analysis reproduced at Exhibit A-1, Claim 1, Element 5 electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.

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area of the substrate where there are no active regions; and	
[Claim 21, Element 1g] at least one well region adjacent to the first or second active region containing at least one graded dopant region, the graded dopant region to aid carrier thereof movement from the surface to the area of the substrate where there are no active regions, and wherein the graded dopant concentration is linear, quasilinear, error function, complementary error function, or any combination thereof.	The Western Digital Accused Products meet this limitation. <i>See</i> above at Claim 1, Element 1g; Exhibit A-3, Claim 21, Element 6. <i>See also</i> SRP analysis reproduced at Exhibit A-1, Claim 1, Element 5 electrically characterizing the accused product and showing carrier movement and electric fields. SRP analysis generally is discussed at Exhibit A-1, Claim 1, Element 5.
23. The system of Claim 21, wherein the substrate of the at least one semiconductor device is a ptype substrate.	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 23.
24. The system of Claim 21, wherein the substrate of the at least one semiconductor device has epitaxial silicon on top of a nonepitaxial substrate.	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 24.
25. The system of Claim 21, wherein the first active region and second active region of the at least one semiconductor device contain at least one of either p-channel and n-channel devices.	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 25.
26. The system of Claim 21, wherein the first active region and second active region of the at least one semiconductor device contain either p-channel or n-channel devices in n-wells or p-wells, respectively, and each well has at least one graded dopant.	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 26.
27. The system of Claim 21, wherein the first active region and second active region of the at least	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 27.

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one semiconductor device are each	
separated by at least one isolation region.	
28. The system of Claim 21,	The Western Digital Accused Products meet this limitation. See Exhibit A-3, Claim 28.
wherein dopants of the graded	
dopant concentration in the first	
active region or the second active	
region of the at least one	
semiconductor device are either p-	
type or n-type.	